TABLE 1-1
SORTED
BY
SUBJECT

Table 1-1

Digital Standards and 7665 Specifications

Categorized by Subject and Areas of Interest

(Status as of 27-Mar-81)

Notes

(*) Indicates that there is a Change in process or planned. Refer to EL & 7665 Index, Section 0 for details.

DOC I.D. formats 022 = DEC STD 022
S022 = 7650022

Table 1-1. **Digital Standards, Manuals, and 7665XXX**
Categorized By Subject And Areas Of Interest

TITLE	DOC I.D.
CABLE/WIRE SPECS	
Cable and Harness Drawings	022
Workmanship Requirements	116
Wire Insulation Pull Test - Q.C. Procedure	5047
Cable Location Marking - Manufacturing Standard	5111
Solderless Crimped Terminations - Controls & Procedures	5267
Cable/Harness Standard Times By Operation Codes	5317
Repair Procedure For Wire Insulation and/or Conductor Damage	5332
Cable/Harness Assembly Process Handbook	5339
CALIBRATION SPECIFICATIONS	
Wire-Wrap Tooling Calibration Q.C. Procedure	5027
OPCOA Automatic L.E.D. Tester - Q.C. Procedure	5074
Flip Chip Cable Tester Calibration	5116
Hardigg Shock Table Calibration - Q.C. Procedure	5130
Hewlett Packard Type 6253A D.C. Power Supply Calibration Calibration Q.C. Procedure	5132
Calibration, Maintenance, and Control of Test and Measurement Equipment	5141*
Sheffield Cordax Measuring Machine Calibration Procedure	5246
Optical Comparator Calibration Procedure	5261
Solderless Crimped Terminations - Controls & Procedures	5267
Teradyne T317 Acceptance and Accuracy Test Procedure	5272

Table 1-1. (Cont'd)

TITLE	DOC I.D.
CALIBRATION SPECIFICATIONS (Cont'd)	
Wire Crimp Tester - Calibration Procedure (DEC Drawing #9305475	5273
Calibration Facility Audit Checklist	5319
COMPONENT ENGINEERING SPECS	
Diode Forward Recovery Test Setup	5065*
Operating Instructions for Water Bath Thermal Shock & Drying Oven	5066
Handling and Assembly of Electro-Static Sensitive Devices	067*
DEC Integrated Circuit Test System	5160
Acceptance Test Procedure - Teradyne Pulse Parametric Test System S257S	5162
Automatic Handler Attachment For Teradyne S257S Test System	5163
Teradyne J259/S257S Operating Procedure	5164
Specification of Liquid Medium Thermal Shock Chamber	5182
Magnetic Tape Cleaning/Testing Procedure	5184
Component Engineering Life Test System-Performance Specification	5196
Process Compatibility Test Methods	5212*
J384 System Specification	5230
Miniature & Subminiature Incandescent Lamps	5251
Process Requirements For AMPMODU MOD 1 Receptacles and Posts For Mated Modules	5258
"Selection and Specification" - Guideline For Connectors/ Interconnecting Components	5260

Table 1-1. (Cont'd)

TITLE	DOC I.D.
COMPONENT ENGINEERING SPECS (Cont'd)	
Continuity Test - Integrated Circuits	5269
Data I/O V Programming Capabilities For PROMS	5274
S260 Test Specification - Test Capabilities For TP1 Wafer	5275
Operating Instructions For The Electrogals 1034 Wafer Prober	5276
SSI S3260 Operating Procedure	5307
"PAVES" - Instructions For Completing "Transfer and Flow Form" (81-110-31)	5314
Vendor Material Deviation Request	5340*
Instructions For Completing "Transfer and Flow Form"	5344
CUSTOMER SERVICES SYSTEMS ENGINEERING (CSSE)	
Hardware Manual Standard	003
Circuit Design Guidelines	007
Project Scheduling System	008
Project Specification	009
Engineering Change Orders	100*
Field Maintenance Print Sets	117
Product Safety	119*
Reliability Prediction	139
Error Logging	153*
Field Returns-Inspection Criteria	264

Table 1-1. (Cont'd)

TITLE	DOC I.D.
DESIGN/DRAFTING SERVICES	
Part and Document Naming Conventions	006
Checking of Drawings	010*
Digital Corporate Policy on Part and Document Identification Conventions	012*
Sizes and Formats	013
Drawing Revisions	014
Abbreviations	015*
Casting Standards	020
Cable and Harness Drawings	022
Drawing Directory	024
Parts List	025
Logic Symbology, Circuit Schematics	056
Engineering Change Orders	100*
Dimensioning and Tolerancing	114*
Packaged Systems Documentation Structure	126
Module Documentation (Structure)	140
Printed Circuit Release Flow	142
Engineering Documentation Acceptance Criteria	182
Archiving Microcode in the Engineering Documentation System	183
Documentation of Computer Media in the Engineering Documentation System	185*
Archiving Engineering Information: Policy and Procedures	188

Table 1-1. (Cont'd)

TITLE	DOC I.D.
DOCUMENTATION	
Hardware Manual Standard	003
Microfilm Aperture Cards - Creation and Distribution Process	033
Purchase Specifications	055
Engineering Change Orders	100*
Field Maintenance Print Sets	117*
Packaged System Documentation	126
Integrated Circuit Documentation and Test Systems Control	133
Module Documentation	140
Digital Magnetic Tape Labels and File Structure Standard	149
Micrographics: Format and Quality Requirements for Microforms	162
Standard for Documentation Symbology	165
Wirewrap Backplane and Wirewrap Module Release Process	181*
ROM/PROM Documentation: Process and Requirements	184*
Documentation of Computer Media In The Engineering Documentation System	185*
Legal Guidelines for Digital Publications	197

Table 1-1. (Cont'd)

TITLE	DOC I.D.
HARDWARE ENGINEERING, DESIGN	
VAX Architecture Standard	032
Standard Coded Character Set	051
Engineering Change Orders	100*
Environmental Standard for Computers And Peripherals	102*
Digital Standard For Terminal Keyboards	107
DEC Standard for Escape Sequence	110
DEC Standard for Terminal Synchronization	111
Dimensioning and Tolerancing on Engineering Drawings	114*
Product Safety	119*
Cooling Standard	120*
Packaged System Documentation	126
Standard for the Registration of Control Characters, Escape Sequences, and Control Sequences	138
Module Documentation	140
Printed Circuit Release Flow	142
Digital Equipment Corporation Hardware and Software Editing Standard	147
User Mode Diagnostic Standard	148
Punched Card Format	151
PDP-11 Extended Instructions	168

Table 1-1. (Cont'd)

TITLE	DOC I.D.
HARDWARE ENGINEERING, ELECTRICAL	
AC Power Wiring and Receptacles	002
Digital Policy Requiring Hardware Products To Be Certified and Designed To National and International Regulations	060
Environmental Standards for Computers and Peripherals Electromagnetic Compatibility (EMC), Radio Interference (RFI) Emissions, Electromagnetic Interference (EMI), Electrostatic Discharge (ESD): Requirements	102*
Product Safety	119*
AC Power Line Standard	122*
Power Control Bus	123
Signal Integrity	186
HARDWARE ENGINEERING, LOGIC DESIGN	
Circuit Design Guidelines	004
Logic Symbology - Circuit Schematic	056
Printed Circuit Release Flow	142
Omnibus Specification	157
Unibus Specification	158
Massbus Interface Specification	159*
LSI-11 Bus Specification	160*

Table 1-1. (Cont'd)

TITLE	DOC I.D.
INSPECTION, QUALITY CONTROL	
Products Non-Compliant with Digital Standards: Reporting Procedure and Waiver Process	005*
Checking of Drawings	010*
Incoming Inspection Procedure	059*
Finish and Color Standard	092*
Environmental Standard for Computers And Peripherals	102*
Standard for In-House Acceptance Procedures	106
Workmanship Manual	116
Digital Product Safety	119*
Integrated Circuit Documentation and Test System Control	133
Disk Standard for Recording and Handling Manufacturing Detected Bad Sectors	144
MANUALS	
Hardware Manual Standard	003
Field Maintenance Print Sets	117*
Standard for Indexes, Appendices, Running Heads and Section Numbering for Software Manuals	118
Format Standard for Manuals Produced On Typeset Media	124
Standard For Updating Manuals Hardware/Software	143
Standard Order for Front and Back Pages of Manuals	146
Standard For Documentation Symbology	165
Standard for Documenting Systems Messages	170
Legal Notices Required for Software Manuals and Licensed Software Sources	172

TITLE	DOC I.D.
MANUFACTURING	
Products Non-Compliant with Digital Standards: Reporting Procedure and Waiver Process	005*
Digital Corporate Policy on Part and Document Identification Conventions	012*
Module Manufacturing Standard	030*
Module Rework and Repair Standard	265
Option Serialization and Identification	031*
Standard Coded Character Set	051
Field Return of Defective Material - Inspection Procedure	264
Finish and Color Standard	092*
Engineering Change Orders (ECOs)	100*
Manufacturing Operations Plan for Assembly, Inspection, and Testing	101
Dimensioning and Tolerancing on Engineering Drawings	114*
Numbering Control System for Manufacturing Process Documentation	115*
Workmanship Standards Manual	116
Field Definitions of the Volume Manufacturing Master Parts File	137*
Printed Circuit Release Flow	142
Disk Standard For Recording and Handling Manufacturing Detected Bad Sectors	144
Digital Marking Standard	178
Powder Metal Bearings and Bushings	179
Wirewrap Backplane and Wirewrap Module Release Process	181*

Table 1-1. (Cont'd)

TITLE	DOC I.D.
MECHANICAL PROCESS SPECS	
Motor Balancing - Mfg. Standard	5020
Hardware Assembly Standard - Q.C. Procedure	5099
General Torque Requirements	5328
METAL FAB/FINISH SPECS	
Finish Specification - Q.C. Procedure	5019*
Chromicoat & Irridite Finish - Touch-up	5022
Control of Fixtures Used In Fabrication Ships - Q.C. Procedure	5060
Chromate Conversation Coating For Aluminum Alloys	5170
Process Spec. For Iron Phosphate Iron On Cold Roll Steel	5171
Workmanship Standard Specification - Metals Business Procedure	5213*
Installation and Operating Instructions For Automated Degreasers Model HL-600	5214
Silk Screen Artwork Procedure Process Specification	5233
Process Spec. To Apply Vinyl Baked Enamel	5262
Touch-Up Procedure For Air Dry and Aerosol Paints	5303
Zinc Plating and Chromate Inspection Procedure (NEW SPEC IN PROCESS)	5333
Supplier Quality Survey - Metals Fab.	5345-0
Vendor Information Summary	5345-1
Supplier Quality Survey-General	5345-2
Special Process Survey-Castings	5345-3

Table 1-1. (Cont'd)

TITLE	DOC I.D.
METAL FAB/FINISH SPECS (Cont'd)	
Special Process Survey-Chemical Finishes	5345-4
Special Process Survey-Plastics	5345-5
MODULE SPECS	
Touch-up Specification	5010
Procedure For Identifying Multiple Used Boards Without Handles	5029
Final Module Inspection Procedure	5039
Procedure For Use of Module Inspection Gages (To be combined with drawing #93-05766)	5042
Standard Vibration Test On Flip Chip Systems	5057
Solder Wave Manufacturing Process Procedure/Specification	5158*
General Radio 1792A Module Tester	5224-0
Acceptance Procedure For GR1792A Test Systems	5224-1
GR Module Test Program Request Procedure	5224-3
General Radio Module program Generation Procedure	5224-4
Generalized GR 1792A Start-Up and Operation Procedure	5224-5
CAPS Diagnostic Message Interpretation	5224-6
Module Repair Area	5224-7
GR1792A Logic Circuit Tester - Preventative Maintenance	5224-8
Release Procedures For GR 1792A (CAPS V) Subassembly Diagnostics	5224-9
General Radio 1792A Preventive Maintenance Procedure	5224-10

Table 1-1. (Cont'd)

TITLE	DOC I.D.
MODULE SPECS (Cont'd)	
Machine Insertable Component Categories For Computer Controlled Inserters	5228*
XOR Testing of CMT Modules - Test Procedure	5234
Sequencer Output Centering Requirements - Procedure	5270
Cherry "Q" Rivet (Self Plugging) Procedure	5271
Machine Performance Data Collection Procedure	5278
Axial Component Sequencer System - Operation Procedure	MFSEQ
C/C Sequence Machine Preventive Maintenance - Procedure	5280
C/C V.C.D. Component Insertion - Procedure	MFVCD
C/C VDC Insertion Machine Preventive Maintenance Procedure	5282
C/C Loose DIP Insertion Operation - Procedure	MFDIP
C/C DIP Inserter Preventive Maintenance Procedure	5284
Fixed Head .01 Axial Lead Insertion Operation - Procedure	5285
.01 Axial Lead Machine Adjustments & Preventive Maintenance - Procedure	5286
Aqueous Cleaning System Acceptance Procedure	5290
Installation, Operation, and Maintenance Procedure For Hydrokleen III Aqueous Detergent System Model 1-18	5291*
Hollis Astra Wave Soldering System Specification	5295
Printed Circuit Board Modules Cleaning Contamination	5299
Standard Module Defect Codes and Descriptions	5304
Loose Components Taping Machine Operation Procedure	5306

Table 1-1. (Cont'd)

TITLE	DOC I.D.
MODULE SPECS (Cont'd)	
Digital Module Assembly Process - Handbook	MF308
Solder Mask Requirements For H2D (Fine Line) Modules	5316
Fast Mask Hollis Conveyorized Solder Machine	5325
C/C BF/V.C.D. Component Insertion Operations - Procedure	5337
PCB SPECS	
Alignment of Gold Contacts on Circuit Boards - Inspection Procedure	5002
Solder Mask - Process Specification	5004
Gold Plating - Process Specification	5005
Solder Mask Panels - Inspection Procedure	5006
PC Board Drilled Hole Size vs. Component	5007
Printed Circuit Board Thickness - Inspection Procedure	5008
Plated Through Hole Panels Inspection Criteria - Inspection Procedure	5009
Single Sided Panels Inspection Criteria - Inspection Procedure	5026
Workmanship Criterion Contact Appearance of Printed Circuit Boards	5051
Emulsion Protection System	5178
Solder Resist Application	5189
36 Inch Rotary Slitter - Installation Procedure	5263-0
36 Inch Rotary Slitter - Operation Procedure	5263-1
36 Inch Rotary Slitter - Design Specification	5263-2

Table 1-1. (Cont'd)

TITLE	DOC I.D.
PCB SPECS (Cont'd)	
Printed Circuit board Gold Contact Cleaning - New Process	5266
Special Digital/DI-ACRO 24" Module Hand Shear - Operation Procedure	5301
POWER SUPPLY/POWER CONTROL SPECS	
Test Procedure Format For Power Supplies	5024
Delay Timer (P. Sup. - P. Ctrl.) How to Connect It and How It Works	5030
Power Supply - Control Model Acceptance - Q.C. Procedure	5031
Requirements and Workmanship Standards For Power Supplies	5038
General Design Guide For Power Supplies and Power Controls	5095
Guidelines For Writing A Power Supply Test Requirements Specifications	5305
PROCESS EQUIPMENT PURCHASE SPECS	
Aqueous/Detergent Cleaning System Purchase Specifications	5289
Purchase Spec. Hollis Wave Solder Equipment	5309
Purchase Specification Aqueous Tower Scrubber	5312
Purchase Spec. Smog Hog Hollis Venting	5313
Purchase Spec. Transfer Conveyer	5315
PRODUCT SAFETY SPECIFICATIONS	
Engineering Test BT34B - Resistor Flameproof Specification	5253*
Electrical Safety Product Test Procedure	5277

Table 1-1. (Cont'd)

TITLE	DOC I.D.
System Safety Grounding Procedure	5300
Abbreviated Hypot Test Procedure	5302
PROJECT MANAGEMENT	
Digital Standards	001
Hardware Manuals	003
Design Review	007
Project Scheduling	008
Project Specifications	009
Digital Policy Requiring Hardware Products To Be Certified and Designed To National and International Regulations	060
Manufacturing Operations Plan for Assembly, Inspection, and Testing	101*
Confidential Engineering Information: Policy and Requirements	128
Guide for Product Business Plans - Marketing Committee/OOD Interface	130*
Engineering Notebook Policy and Requirements	141
QUALITY ASSURANCE SPECS	
Date Coding Material	5064
Corrective Action Request Procedure	5069
Incoming Inspection Operating Procedure	5073*
Procedure For Processing Non-Conforming Material and In-Process Waiver	5075
Procedure For ECO Status Sheet	5077

Table 1-1. (Cont'd)

TITLE	DOC I.D.
QUALITY ASSURANCE SPECS (Cont'd)	
Acceptance Stamps - Use and Control Procedure	5096*
Format Procedure For Writing Engineering Specifications	5287
Quality Assurance Operational Alert/Product Hold Procedure	5298*
In-Plant Product Safety Hold	5310*
Procedure For Handling Government Source Inspection Acceptance	5322
Government Pre-Award Survey Proc	5323
Procedure For Assessing Mfg. Syst.	5326
Product Certification Policy	5327
Ship Cost Analysis	5327
Ship To Stock Supplier Quality Program - Audit Guideline For Plan Quality Engineer	5347
Ship To Stock Supplier Quality Program - Basic Agreement and Release Procedure	5348
RELIABILITY ENGINEERING SPECS	
Process Maturity Test Spec.	5268-0
Design Maturity Test Specification	5268-1
On-Going Reliability Assurance Procedure	5296*

Table 1-1. (Cont'd)

TITLE	DOC I.D.
SOFTWARE ENGINEERING	
VAX Architecture Standard	032
Standard Coded Character Set	051
Digital Standard For Terminal Keyboards	107
Escape Sequences	110
Terminal Synchronization	111
Standard Date Format for Output	112
Digital Data Communications Message Protocol (DDCMP)	121
Cassette Format Standard for Labelled/Unlabelled Files	125
Standard For The Registration of Control Characters, Escape Sequences, and Control Sequence	138
Disk Standard for Recording and Handling Manufacturing Detected Bad Sectors	144
Digital Equipment Corporation Hardware And Software Editing Standard	147
User Mode Diagnostic Standard	148
Digital Magnetic Labels and File Structure Standard	149
BASIC	150
Punched Card Format	151
COBOL	152
Error Logging Standard	153

TABLE 1-2
SORTED BY KEY WORDS

Table 1-1. (Cont'd)

TITLE	DOC I.D.
SOFTWARE ENGINEERING (Cont'd)	
Volume Identification for Removable Disk Pack Disk Systems	167
PDP11 Extended Instructions	168
Standard for Documenting Systems Message	170
Legal Notices Required for Software and Manuals Licensed Software Sources	172
Magnetic Tape Error Recovery Procedures For Read And Write Errors	174
SYSTEM MANUFACTURING SPECS	
Use and Application of The Actual Cost Jobs Closes Or Transfers	5254
Shipping Tag	5293*
Customer Envelope Paperwork Req.	5294*
Preliminary Documentation Postcard Procedure	5341
Test Requirements For Equipment Released From Z Stock	5342
Installation Audit Procedure	5349*
System Manufacturing Final Product Audit Plan	5350
TEST METHODS, COMPONENT	
Procedure For Answering Question "C" On The PRNF	0P-PRNF
Test Method For Visual Compliance	TM-002A
Test method For Mechanical Dimensions	TM-002B
Test Method For Marking Permanence	TM-002C
Test Method For Solder Heat	TM-002D

Table 1-1. (Cont'd)

TITLE	DOC I.D.
TEST METHODS, COMPONENT (Cont'd)	
Test Method For Solderability	TM-002E
Test Method For Lead Pull	TM-002F
Test Method For Lead Bend	TM-002G
Test Method For Package Integrity, Thermal Liquid	TM-002I
Test Method For Pressure Cooker Test	TM-002J
Test Method For Gross Leak	TM-002L
Test Method For Flammable Plastics	TM-002N
Test Method For Marking Permanence, Thermal	TM-002T
Test Method For Package Integrity, Detergent	TM-002U
Test Method For Package Integrity, Thermal Air	TM-002V
Test Method For Constant Acceleration	TM-002W
Test Method For Auto Test	TM-004G
Test Method For Leakage Current	TM-04LF
Test Method For AC Dielectric Withstanding Voltage	TM-04TB
Test Method For Turns Ratio	TM-04TD
Test Method For Excitation Current	TM-04TE
Test Method For Polarity	TM-04TG
Test Method For DC Resistance	TM-04TJ
Test Method For Inductance	TM-04TK
Test Method For Leakage Inductance	TM-04TS
Test Method For Winding Continuity	TM-04TT

Table 1-1. (Cont'd)

TITLE	DOC I.D.
TEST METHODS, COMPONENT (Cont'd)	
Test Method For Nominal Speed	TM-05AE
Test Method For Hall Effect and Speed	TM-05AI
Test Method For Normal Force	TM-05BB
Test Method For Contact	TM-05BH
Test Method For Functional Operation	TM-05CA
Test Method For DC Dielectric Withstanding Voltage	TM-05RL
Test Method For Contract Resistance	TM-05TB
Incoming Inspection Test Requirement File	TR-0TRF
WIREWRAP/BACKPLANE SPEC	
Wire-Wrapped Panel - Inspection Procedure	5001
Resistance Soldering - Process Specification	5012
Wire-Wrap Process Specification and Inspection Procedure	5013
Layout Specification For Printed Circuit Back Panels	5028
DEC Semi-Automatic Wire Wrap Operations Manual	5033
Repairing Damaged Connector Blocks and Backplane Assemblies	5034
BUS Splicing	5098
Operating Specification For Twisted Wire Stripper	5159
Printed Circuit Backplane Soldering Procedure/Process Specification	5236

Table 1-1. (Cont'd)

TITLE	DOC I.D.
WORKMANSHIP SPECIFICATIONS	
Wire-Wrap Process Specification and Inspection Procedure	5013
Final Module Inspection Procedure	5039
Workmanship Criterion Contact Appearance of Printed Circuit Boards	5051
Memory Circuit Boards - Acceptance Standards	5052
Hardware Assembly Standard - Q.C. Procedure	5099
8/E OMNIBUS Inspection and Acceptance Procedure	5119
H851 Edge Connector Mechanical Inspection and Acceptance Procedure	5121
Printed Circuit Backplane Soldering Procedure/Process Specification	5236
Module Rework and Repair Specification	265
Solderless Crimped Terminations - Controls and Procedures	5267

Table 1-2

Information Locator

Digital Standards,

7665 Specifications
and
Related Industry/DEC

Documents (under

DEC STDs Control)

Categorized by Subject

Keywords

(Status as of 27-Mar-81)

<u>THIS IS A PARTIAL INDEX</u>
<u>AND STILL UNDER DEVELOPMENT</u>

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Subject	Reference	Subhead or other (as indicated)
Abbreviations	DEC STD 015	
AC Design Rules, Gate Array Design	ELMP400-UG	s 4
AC Parameter Testing, Sampling Plan	7665357-00	
AC Power Receptacles	DEC STD 002	
AC Power Wiring	DEC STD 002	
Acceptance Criteria,		
Engineering Documentation	DEC STD 182	
Plotted Master Artwork	DEC STD 034	
Printed Wiring Board	DEC STD 176	
Acceptance Stamps	7665096-00	
Acoustic Noise,		
Product-Acceptability	DEC STD 10[illegible]	
Actual Cost Job Closing	7665254-00	
Adhesion Test,		
Gold Plating of Contacts	7665005-00	s 4.5
Adjacent Pads, Interconnection	DEC STD 030	rule 5180
AICT/PDP-7		
A/D, Calibration Procedure	7665063-00	
Integrated Test, Setup Procedure	7665061-00	
Air Miter Eyeletting Press	ELMF308-04	s 4.2
Alignment,		
Fixture - Seg Centering Device	ELMF308-01	s 3.5.2
Gold Contact-Inspection Procedure	7665002-00	
Alignment Bar - Work holder, Module	ELMF308-01	s 3.4.2
ALM (Assembly Library Module)	ELEN302-00	s 5.2
All Inclusive Assembly Process		
Flow Diagram	ELMF308-00	figure 1
Alodine Finish,		
Touch-up	7665022-00	
Aluminum Sheet Metal-Chromicoat		
Finish, QC Procedure	7665019-00	
Alva Allen 2-ton Press	ELMF308-04	s 3.2
American Wire Gauge (AWG)	DEC STD 116-8	s 5.0
AMP Mate-N-Lok Bending Tool	ELMF308-01	s 2.3
AMP MODU Mod 1 - Receptacles/Posts	7665258-00	
AMP Spring Socket Machine	ELMF308-01	s 3.9
Angle Iron and Plate Calibration	7665059-00 (Obsolete)	
ANSI X.34-1968	DEC STD 051	
Anti-Static Kit DIP Machine	ELMF308-01	s 3.4.2

Subject	Reference	Subhead or other (as indicated)
Anti-Static Work Stations	ELMF308-02	s 2.4.1
Anvils-Eyelet Machine	ELMF308-01	s 3.2.3
Anvils-Split Lug Machine	ELMF308-01	s 3.3.3
Applicon Library, General Description	ELEN302-00	s 6.1
Aqueous		
Cleaner	ELMF308-03	s 2.5
Defoamer	ELMF308-03	s 2.5.3
Descaler	ELMF308-03	s 2.5.3
Detergent	ELMF308-03	s 2.5.3
Floor Layout	ELMF308-03	figure 2
Operating Specifications	ELMF308-03	s 2.5.3
Archiving Engineering Information	DEC STD 188	
Artwork,		
Negative Plotted	DEC STD 030	rule 5320
Optimization	DEC STD 030	figure 23
Plotted Master	DEC STD 034	
Positive-plotted	DEC STD 030	figure 23
Requirements, multilayer	DEC STD 030	s 5.4
ASCII Character Strings,		
Data Values	DEC STD 145	
Assembly,		
Aids	ELMF308-02	s 2.4
Checking Considerations	DEC STD 010	s 1.11
Library Module (ALM)	ELEN302-00	s 5.2
Manufacturing Operations Plan	DEC STD 101	
Pass Down Line	ELMF308-02	figure 1
Pin Identification	DEC STD 116-8	s 4.2.2
Process Applicable documentation	ELMF308-00	s 1.4
Process Flow Diagram	ELMF308-00	s 2
Wirewrap Panel-Inspection	7665001-00	
Assignment of Discrete Component Reference Designators	DEC STD 030	rule 6150
Assignment Process, 74-Class Part Identifiers	DEC STD 012-7	s 3
Authorized Returns List (ARL)	DEC STD 264	s 2.1.1
Auto-insertable Components, Use in PC Designs	DEC STD 030	rule 4031
Automatic Component Insertion		
Axial Fixed Head Inserter Operator Procedure	7665285-00	
Axial Fixed Head Inserter Preventative Maintenance	7665286-00	
Axial VCD Inserter Gen 3, Operator Procedure	MFVCD-OP-3	
Axial VCD Preventative Maintenance	7665282-00	
Component Codes and Categories	7665228-00	
DIP Inserter Gen 3 Operator Procedure	MFDIP-OP-3	

Subject	Reference	Subhead or other (as indicated)
DIP Inserter Preventative Maintenance	7665284-00	
Sequencer Gen 5 Operators Procedure	MFSEQ-OP-5	
Sequencer Output Centering Procedure	7665270-00	
Sequencer Preventive Maintenance	7665280-00	
Automatic Inspection - Zehntel	ELMF308-05	s 2.2
Automated Positioning Table Board Slitter	ELMF308-04	s 2.2
Axial Components,		
Auto-Inserted	DEC STD 030	table 8, rule 4030
Sequencer	ELMF308-01	s 3.5
Axial Lead		
Axial Lead Capacitor Insertion	ELMF308-01	s 3.7
Axial Lead Component, Insertion Codes		
Standard .200-Inch Pitch	7665228-00	s 6
Large Bodied .375 - .400 Inch Pitch	7665228-00	s 7
Axial Lead Component Preformer	ELMF308-01	s 2.1
Axial Lead Insertion, VCD	ELMF308-01	s 3.6

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BBBB
B   B
BBBB
B   B
BBBB
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Subject	Reference	Subhead or other (as indicated)
Backpanel		
Acceptance Stamps	7665012-00	
Assembly Rules	DEC STD 030	s 8.3
Bus Splicing	7665034-00	
Definition of types	DEC STD 030	p 74
Identification, 8/I	7665014-00	
Press-pin, Design Rules	DEC STD 030	s 8.2
Printed Circuit Layout	7665028-00	
Repairing Damaged Assemblies	7665096-00	
Resistance Soldering	7665098-00	
Size, Finished Board	DEC STD 030	rule 8000
Soldering Process/Procedure	7665236-00	
Soldermask	DEC STD 030	rule 8010
Wave-Soldered, Design-Rules	DEC STD 030	s 8.2
Backplane		
Castings	DEC STD 030	s 8
Finished Board Size	DEC STD 030	rule 8430
Layout Rules	DEC STD 030	s 8
Line Width & Spacing	DEC STD 030	rule 8400

Subject	Reference	Subhead or other (as indicated)
Backplane (cont'd)		
Mounting Bars	DEC STD 030	s 8, rule 8120 figure 40
PC Layout Rules	DEC STD 030	s 8
Pre-Design Producibility Form	DEC STD 030	figure 4
Press Pin	DEC STD 030	s 8.7
Repair, Inspection	7665034-00	
Standard	DEC STD 030	s 8.1.1
Test Rules	DEC STD 030	s 8.4
Test System	DEC STD 030	rule 8610
Thickness	DEC STD 030	rule 8630
Types of	DEC STD 030	s 8.1
Wirewrap Process, Inspection	7665013-00	s 8.4
Bad Board Sticker	ELMF308-01	s 3.6.3
Baking Oven-Small, Module	ELMF308-03	s 2.1
Baking Oven - Walk-in	ELMF308-03	s 2.2
Bar Solder	ELMF308-03	s 2.3.3
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Bed of Nails- UBON	ELMF308-05	s 2.2.2
Bending Tool for AMP Mate-N-Lok Pin	ELMF308-01	s 2.3
Bends, 90°	DEC STD 030	rule 5185
Bend Radius, Wire and Cable	DEC STD 116-3	s 4.0
Berg Pin Insertion	ELMF308-01	s 3.10
Blow Hole, Touchup Requirements	7665010-00	s 2.4
Blue Tape 0.25 inches x 180 yards	ELMF308-01	s 2.4.2
Blue Tape 0.25 inches x 3,520 yards	ELMF308-01	s 3.5.3
Board, PC, Overview	DEC STD 030	figure 8
Board Slitter	ELMF308-04	s 2.2
Board Slitter-Automated Positioning Table	ELMF308-04	s 2.2
Body Form Variable Center Distance (BFVCD), Machine Setups	7665228-00	s 6.2.2
Bond Strength Test, Wire Insulation	7665047-00	
Bus Requirements,		
LSI Bus	DEC STD 160	
Massbus	DEC STD 159	
Omnibus	DEC STD 157	
Unibus	DEC STD 158	
Bus Separations	DEC STD 030	rule 5330
Bus Splicing	7665098-00	

Subject	Reference	Subhead or other (as indicated)
Business Plans, Product	DEC STD 130	
BX Part Number	DEC STD 129	s 2.1.1
Bypass Capacitor Selector	DEC STD 030	rule 6110

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Cabinet, Thermal Calculations	DEC STD 120	
Cable,		
Acceptance Stamps	7665096-00	
Assembly Identification	7665045-00	
Documentation	DEC STD 022	
Flat Conductor	DEC STD 116-2	s 10.0
Workmanship Standard	7665049-00	
Clamps	DEC STD 116-4	s 11.4
Flip Chip Tester	7665116-00	
Location Marking	7665111-00	
Solderless Crimpled Terminations	7665267-00	
Cables and Harness, Workmanship Criteria	DEC STD 116-4	
CAD Layout Tools, Gate Array Design Verification	ELMP400-UG	s 5.2
CALDEC Library,		
File Name Format	ELMF302-00	s 3.7
General Description	ELMF302-00	s 3.1
"L" Number Assignment	ELMF302-00	s 3.1
Calibration, Electrical	7665063-00	
Baird-Automatic Model OT-IH	7665133-00 (obsolete)	
Datapulse 101 Pulse Generator	7665135-00 (obsolete)	
Flip Chip Cable Tester	7665116-00	
Hardigg Shock Table	7665130-00	
Hewlett Packard 200 CD	7665103-00 (obsolete)	
Hewlett Packard 6253A DC PowerSupply	7665132-00	
OPCOA Auto LED Tester	7665074-00	
Tektronix 106 Square Wave Generator	7665107-00 (obsolete)	
Tektronix 109 Pulse Generator	7665108-00 (obsolete)	
Tektronix 130 EC Meter	7665104-00 (obsolete)	
Tektronix 191 Signal Generator	7665109-00 (obsolete)	
Tektronix 453 Oscilloscope	7665094-00 (obsolete)	
Tektronix 575 Oscilloscope	7665106-00 (obsolete)	
Tektronix P6045 Probe	7665134-00 (obsolete)	
Calibration,		
General Requirements	7665141-00	

Subject	Reference	Subhead or other (as indicated)
Calibration, Mechanical		
Angle Iron and Plate	7665059-00 (obsolete)	
Auto/Semi-Auto Crimping Tools	7665239-00 (obsolete)	
Depth Micrometer	7665055-00 (obsolete)	
Dial and Test Indicator	7665058-00 (obsolete)	
Dial Vernier	7665053-00 (obsolete)	
Hand Crimping Tools	7665237-00 (obsolete)	
Optical Comparator	7665261-00	
Outside Micrometer	7665043-00 (obsolete)	
Parallel Bar	7665046-00 (obsolete)	
Plain Plug Gauge	7665040-00 (obsolete)	
Push/Pull Gauge	7665048-00 (obsolete)	
Sheffield Cordax Measuring Machine	7665246-00	
Universal Dial Test Indicator	7665137-00 (obsolete)	
Vernier Caliper	7665054-00 (obsolete)	
Wirewrap Tooling	7665027-00	
Wirecrimp Tester	7665273-00	
CALMA, Gate Array Design	ELMP400-UG	s 1.3.1.4
Camera Back	7665181-00	
Capability Manufacturing, Modules	DEC STD 030	table 4
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Axial lead Insertion Machine	ELMF308-01	s 3.6,3.7
Bypass	DEC STD 030	rule 6110
Decoupling	DEC STD 030	rule 6120,figure 36
Insertion - Axial Lead	ELMF308-01	s 3.6, 3.7
Layout Rules	DEC STD 030	rule 6120,figure 36
Low-Pass Filter	DEC STD 030	rule 6130
Polarized	DEC STD 116-1	s 20.0
Polarized-Identification	DEC STD 116-8	s 2.2
Selection Assistance	DEC STD 030	table 7
Tantalum	DEC STD 030	rule 4000
Tantalum, Not for PC Design	DEC STD 030	p 36, rule 4000
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Drawings	DEC STD 020	
Standard, Backplane	DEC STD 030	rule 8100
CCITT V.28, Binary Interfaces	DEC STD 053	
Cell, Basic Naming Convention, Gate Array	ELMP400-UG	table 2-1
Cell Combinations, Gate Array	ELMP400-UG	s 2.2
Cell Layout, Gate Array	ELMP400-UG	figure 2-1
Centering Device Alignment Fixturing Seq.	ELMF308-01	s 3.5.2
Centigrade to Fahrenheit Conversion	DEC STD 116-8	s 7.0
Ceramic IC Packages	DEC STD 030	rule 4140, 4150, table 10, 11
Certification, Hardware	DEC STD 060	

Subject	Reference	Subhead or other (as indicated)
Change Procedures,		
DEC STD	DEC STD 001-1	
ECO	DEC STD 100	
Change, Serial Number -		
Product Variation	DEC STD 031-1	
Character,		
Size	DEC STD 182	s 2.3
Style and Spacing	DEC STD 182	s 2.4
Character Sets,		
Hardware Printers and Displays	DEC STD 051	
Software Programming	DEC STD 051	
Standard Coded	DEC STD 051	
Character Set Requirements,		
Automated Parts List	DEC STD 025-2	s 3.0
Checking,		
Drawings	DEC STD 010	
Engineering Documents	DEC STD 010	
Chemical		
Classifications	DEC STD 109	
Saefty Data	ELMF308-03	s 2.3.6
Safety Data, Fluxes	ELMF308-03	s 2.3.8.1
Safety Data, Module Process	ELMF308-03	s 2.3.8
Safety Data, Oil	ELMF308-03	s 2.3.8.3
Safety Data, Thinners	ELMF308-03	s 2.3.8.2
Solder Wave	ELMF308-03	s 2.3.3
Cherry "Q" Rivet	7665271-00	
Chip Specifications, Basic Gate		
Array Chip	ELMP400-UG	table 1-1
Chromate (Coating)	7665170-00	
Chromicoat,		
Finish - QC Procedure	7665019-00	
Finish, Touchup	7665022-00	
Inspection	7665003-00	s 3.0
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Bridge	DEC STD 116-1	s 29.0
Design, Guidelines	DEC STD 007	
Module Overview	DEC STD 030	figure 8
Module Technololgy, Standard,	DEC STD 030	table 3
Performance, Design Guidelines	DEC STD 004	
Schematics Release	DEC STD 142-0	
Schematics Requirements	DEC STD 056	
Circuitry		
Acceptance Criteria, Memory Circuit Boards	7665052-00	
Inspection-Plated Thru Hole Panels	7665009-00	s 4.0
Power Supply-Inspection Criteria	7665026-00	
Circular Mil Area (CMA)	DEC STD 116-8	s 5.0
Class Codes Parts	ELENKPL-UG	s 13.4.1

Subject	Reference	Subhead or other (as indicated)
Classification, Chemical and Corrosive Environment	DEC STD 109	
Cleaning,		
PCB	DEC STD 116-1	s 4.0
Detergents, Restrictions for Modules	DEC STD 030	rule 8370
Clearances,		
Between Components and Protrusions	DEC STD 030	rule 6010, figure 33
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Mechanical	DEC STD 030	rule 6100,6101, 6102
Module spacing	DEC STD 030	rule 6010
Requirements, Inner Layers	DEC STD 030	rule 5200
Under Handles	DEC STD 030	rule 6070
Clip - Splice	ELMF308-01	s 3.5.3, 3.6.3
CLM (Component Library Module)	ELEN302-00	s 5.3
COBOL	DEC STD 152	
Cold Solder Joint	DEC STD 116-1	s 30.0
Collapsible Pin	ELMF308-02	s 2.1
Color, Module Handles	7665039-00	
Color Codes,		
Component	DEC STD 116-8	s 3.0
Date Coding Incoming Material	7665064-00	
Wirewrap	DEC STD 116-6	s 3.4
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Combined Positive/Negative Plots	DEC STD 030	p 61
Communications Protocol, DDCMP	DEC STD 121	
Compiler, COBOL Options	DEC STD 152	
Complete Software Box	DEC STD 129	s 2.1.2
Complex (Uniform Shape) Logic Symbols	DEC STD 056-2	
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Body	DEC STD 116-1	s 19.0
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Dented/Deeply Scratched	DEC STD 116-1	s 18.0
De[illegible] Rule Directory	DEC STD 030	s 4.1
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File	7665235-00 (obsolete)	
Height Inspection Gage	ELMF308-01	s 2.1
Identification	DEC STD 116-8	s 2.0
Insertability Specification File (CISF)	7665228-00	s 3.1
Insertion Spacing and Direction	DEC STD 030	rule 6000,figure 31

Subject	Reference	Subhead or other (as indicated)
Component (cont'd)		
J384 Test	7665230-00	
Lead Damage	DEC STD 116-1	s 12.0
Lead Dress	DEC STD 116-1	s 13.0
Lead Forming	DEC STD 116-1	s 14.0
Lead Protrusion	DEC STD 116-1	s 15.0
Lead Sleeving	DEC STD 116-1	s 16.0
Library Module (CLM)	ELEN302-00	s 5.3
Life Test	7665196-00	
Machine Insertable	DEC STD 030	rule 4030
Mounting	DEC STD 116-1	s 17.0
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Non-Machine Insertable	DEC STD 030	rule 4160, table 12
Pin Designation	DEC STD 030	rule 6060
Polarity Markings	DEC STD 116-1	s 21.0
Preformer - Axial	ELMF308-01	s 2.1
Preforming Area	ELMF308-01	s 2.1
Process Compatability	7665212-00	
Radial Lead Mounting With Spacer	DEC STD 116-1	s 17.0
Radial Lead Mounting Without Spacer	DEC STD 116-1	s 22.0
Raised	DEC STD 116-1	s 24.0
Reels - Empty	ELMF308-01	s 3.5.3
Resistor Flame Proof	7665253-00	
Replacement Charts	7665035-00	
Separation Distance	DEC STD 116-1	s 26.0
Spacing and Positioning	DEC STD 030	rule 6000,figure 31
Standard and footprint	DEC STD 030	p 36, rule 4010
Standard Grid	DEC STD 030	s 5.3.1
Taping Machine-Loose Piece	ELMF308-01	s 2.4
Test, Integrated Circuits	7665160-00	
Thermal Calculations	DEC STD 120	
Tilted	DEC STD 116-1	s 27.0
Component Categories,		
Insertable Components	7665228-00	s 2.1
.200-inch Pitch, Axial Leaded	7665228-00	s 6
.300-inch Center DIP	7665228-00	s 8
.375 to .400 Inch Pitch, Large Bodied Axial-Leaded	7665228-00	s 7
.400-inch Center DIP	7665228-00	s 9
.500-inch Center DIP	7665228-00	s 10
Conductor,		
Outer Layers	DEC STD 030	rule 5240
Routing	DEC STD 030	rule 5185
Spacing, Standard Grid for Vias	DEC STD 030	rule 5160
Width, Standard Grid for Vias	DEC STD 030	rule 5170
Conductors,		
Lifted	DEC STD 116-1	s 10.0
Pattern Distribution	DEC STD 030	rule 5292

Subject	Reference	Subhead or other (as indicated)
Conductor/Plating Distribution	DEC STD 030	rule 5292
Conductor Pattern	DEC STD 030	rule 5292
Non-Functional Copper	DEC STD 030	rule 5296
Configuration		
Gate Array Design	ELMP400-UG	s 3.2
PCB Layers	DEC STD 030	rule 5240, 5260 5270, figure 9
Conformance,		
Legal Notices On Software	DEC STD 172	s 1.5
Legal Notices On Publications	DEC STD 197	
Connections,		
Power and Ground	DEC STD 030	figure 19,rule 5020
Logic Symbology	DEC STD 056-4	
Materials and Construction	7665260-00	
Connector,		
Backplane	DEC STD 030	rule 8460
Block, Repair	7665034-00	
External, backplane	DEC STD 030	rule 8140
Pin Numbering	DEC STD 116-8	s 4.0
Contact,		
Appearance, Inspection-Plated Thru Hole Panels	7665009-00	
Appearance-Workmanship Criteria	7665051-00	
Finger	7665051-00	
Finger/Etch (Damage)	DEC STD 116-1	s 3.0
Fingers Solder	DEC STD 116-1	s 41.0
Gold Plate Process	7665005-00	
Power Supply - Inspection Criteria	7665026-00	
Contamination, PCB	DEC STD 116-1	s 4.0
Content, Field Maintenance Print Set	DEC STD 117	
Continuity Tester - Teradyne	ELMF308-05	s 2.3
Continuity/Dielectric Strength Test	7665277-00	
Control Character Registration	DEC STD 138	
Control Sequence Registration	DEC STD 138	
Conveyor Lift System - Wave Solder Machine	ELMF308-03	s 2.3.4
Copper,		
Addition of non-functional	DEC STD 030	rule 5296
Inner layer, backplanes	DEC STD 030	rule 8020
Copper planes, large	DEC STD 030	rule 5290
Copyright Notice,		
Parts Lists	DEC STD 025-1	s 2.7
Digital Publications	DEC STD 197	
Licensed Software	DEC STD 172	s 2.1
Software Manuals	DEC STD 172	s 2.1.2
Software Sources	DEC STD 172	s 2.4.2

Subject	Reference	Subhead or other (as indicated)
Core Memory Stack, Inspection Procedure	7665085-00	
Corporate Producibility, Overview of system	DEC STD 030	s 2.1
Corporate Quality Control Policy	DEC STD 017	
Corrective Action Request Procedure	7665069-00	
Corrosive Environment Classifications	DEC STD 109	
Cost, unit, Standard Circuit Technology	DEC STD 030	table 5
Covers, IDEA - Standard	ELEN302-00	s 5.4
Crazing, Printed Circuit Board	DEC STD 116-1	s 6.0
Crimping	7665237-00 7665239-00	
Solderless Crimped Terminations	7665267-00	
Wire Crimp Tester Calibration	7665273-00	
Critical Material Code, Master Part File Field	DEC STD 137	table 1
Cross-Reference Charts Insertion Codes/Machine Setup		
Axial Components	7665228-00	s 11.1
Dual in-line Packages	7665228-00	s 11.3
Large-Bodied, Axial Components	7665228-00	s 11.2
Large-Bodied, .375-inch Pitch Axial	7665228-00	s 11.5
CS Rev		
Marking Modules Without Handles	7665029-00	
Update Stamping Machine	ELMF308-04	s 3.3
CSS Part Numbering Conventions	DEC STD 012-6	
Curing, Soldermask Panels	7665004-00	s 3.3
Customer Returns Capabilities List (CRCL)	DEC STD 264	s 2.1.2
Customer Return Inspection Criteria		
- Defaced or Marked Modules	DEC STD 264	s 4.5
- Field Modified Modules	DEC STD 264	s 4.4
- General	DEC STD 264	s 2
- Keyboards	DEC STD 264	s 4.1
- Option's	DEC STD 264	s 4.7
- Pluggable Modules	DEC STD 264	s 4.6
- Power Supply Subassemblies	DEC STD 264	s 4.2
- Video Display Terminals	DEC STD 264	s 4.3
Cut Plane, Shearing Boards	DEC STD 030	figure 27
Cutters-Lead-Solder Touch-up	ELMF308-03	s 3
C/C Axial Component Sequencer	ELMF308-01	s 3.5
C/C Looser DIP Insertion Machine	ELMF308-01	s 3.4
C/C VCD Insertion Machine	ELMF308-01	s 3.6

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Subject	Reference	Subhead or other (as indicated)
Data Access Protocol	DEC STD 189	
Data Base,		
Identification	DEC STD 185	
Requirements, wirewrap	DEC STD 030	rule 8210
	DEC STD 181	
	DEC STD 185	
Data Code	DEC STD 030	figure 12
Data Interchange, Floppy Disk	DEC STD 154 (obsolete)	
Data Recording Conventions,		
Removeable Diskpack	DEC STD 167	
RX01 Floppy Disk	DEC STD 154 (obsolete)	
Date Coding Material with Color Stickers	7665964-00	
Date, Standard Format	DEC STD 112	
Datum Referencing	ANSI Y14.5 - 1973	s 5-4
DC Design Rules, Gate Array Design	ELMP400-UG	s 3
DC Loading rules, Gate Array Design	ELMP400-UG	s 3.1
Decoupling Capacitors	DEC STD 030	rule 6110
DECtape,		
KPL	ELENKPL-UG	s 13.2
Volume Interchange Formats	DEC STD 196	
DEC STDS,		
Creation and Change Procedure	DEC STD 001-1	
Format and Style	DEC STD 001-2	
Policy	DEC STD 001-0	
Reporting Non-Compliant Product	DEC STD 005-4	
Defaced Modules, Customer Return Inspection Criteria	DEC STD 264	s 4.5
Defective Material, Repair Acceptance Criteria	DEC STD 264	s 2.1
Defects, Requiring Touchup	7665010-00	s 2.0
Definitions,		
Cable and Harnesses	DEC STD 116-4	s 1.0
Current Pin Label-Symbology	DEC STD 056-7	
Mechanical Fasteners	DEC STD 116-5	s 1.0
PCB Workmanship	DEC STD 116-1	s 1.0
Retaining Hardware	DEC STD 116-5	s 1.0
Safety	DEC STD 116-7	s 1.0
Soldered Termination	DEC STD 116-2	s 1.0
Solderless Crimped Termination	DEC STD 116-3	s 1.0
Technical Data	DEC STD 116-8	s 1.0

Subject	Reference	Subhead or other (as indicated)
Definitions, (cont'd)		
Wirewrap/Logic Assemblies	DEC STD 116-6	s 1.0
Workmanship Standards	DEC STD 116-1	s 1.0
Defoamer - Aqueous	ELMF308-03	s 2.5.3
Degreaser	7665214-00	
Delamination, PCB	DEC STD 116-1	s 5.0
Delay, Gate Array Design	ELMP400-UG	s 4.1
Deletion of Unnecessary Fingers	DEC STD 030	rule 5044
Delay Timer	7665030-00	
Density, Standard Grid	DEC STD 030	rule 5100
Depth Micrometer Calibration	7665055-00 (obsolete)	
Descaler-Aqueous	ELMF308-03	s 2.5.3
Design		
Engineering Responsibilities, PC Design	DEC STD 030	s 1.3.1
For Testability	DEC STD 030	s 7
Guide, Power Supplies and Control	7665095-00	
Maturity Test	7665268-00	
Process, Basic Array Chip	ELMP400-UG	s 1.3
Rating, PDQ code	DEC STD 030	s 2.2
Review Process	DEC STD 007	
Rules, Backplanes	DEC STD 030	s 8.1.2
Rules-Summary Module Mfg. Reqmts.	DEC STD 030	Table 1
Selection, Review, Approval Process	DEC STD 030	Figure 2
Verification Process, Gate Array Design	ELMP400-UG	s 5.1
Designation,		
Connector	DEC STD 030	rule 5042
Discrete Components	DEC STD 030	rule 6170
Finger	DEC STD 030	rule 5042
Module	DEC STD 056	
Pins, PC Design	DEC STD 030	rule 5060
Standard Reference	DEC STD 030	rule 6150
Test Hole	DEC STD 030	rule 6160
Detergent		
Aqueous	ELMF308-03	s 2.5.3
Cleaner	ELMF308-03	s 2.5.3
Safety Data	ELMF308-03	s 2.5.5
Deviation from Standard Grid	DEC STD 030	rule 5080
Dewetting	DEC STD 116-1	s 31.0
Di-Acro		
Hand Shear-6 inch	ELMF308-04	s 2.4
Hand Shear-special 24 inch	ELMF308-04	s 2.5
Diagnostic, User Mode-Standard	DEC STD 148	
Diagonal PC runs, minimum length	DEC STD 030	rule 5185
Dial and Test Indicator Calibration	7665058-00 (obsolete)	
Dial Vernier Calibration	7665053-00 (obsolete)	

Subject	Reference	Subhead or other (as indicated)
Digital Data Communications Message Protocol (DDCMP)	DEC STD 121	
Digital Standards System Policy	DEC STD 001-0	
Dimensioning and Tolerancing, Documentation Practice	ANSI Y14.5 - 1973 DEC STD 114	
Dimensioning,		
For Numerical Control	ANSI Y14.5 - 1973	Appendix
General	ANSI Y14.5 - 1973	s 5-1
Pictorial Drawings	ASA Y14.4 - 1957	s 4-10
Screw Threads	ANSI Y14.6 - 1978	
Dimensions, auto-inserted axial component layout	DEC STD 030	figure 15,rule 4030
Diode, Forward Recovery Testing	7665065-00	
Diodes		
Identification	DEC STD 116-8	s 2.3
Selection for PC Layout	DEC STD 030	figure 15,rule 4030
DIP		
Anti-static Kit (MOS)	ELMF308-01	s 3.4.2
Insertion	ELMF308-01	s 3.4
Insertion Machine - C/C	ELMF308-01	s 3.4
Machine Insertable	DEC STD 030	rule 4140, 4150
Orientation	DEC STD 030	rule 6000
Stick Plug Puller	ELMF308-01	s 3.4.2
Direction, Power and Signal Runs	DEC STD 030	figure 24,rule 5185
Directory of Design Rule Categories	DEC STD 030	table 1
Discrete		
Component Numbering	DEC STD 030	rule 6170
Component, Symbols	DEC STD 056-3	
Disk		
Controller, Requirements	DEC STD 144	
Recording and Handling Mfg Detected Bad Sectors	DEC STD 144	
Diskettes, Volume Identification	DEC STD 154	(obsolete)
Diskpack, Identification Across Systems	DEC STD 167	
Disposition of Inspected Materials, Customer Returns	DEC STD 264	s 5
Distinctive Shape Logic Symbols	DEC STD 056-1	
Distribution Networks, AC Power	DEC STD 122	
DME, Standard Covers	ELEN302-00	s 5.4
Documentation,		
Backplane	DEC STD 193	
Computer Media	DEC STD 185	
Engineering Change Orders	DEC STD 100	
Field Maintenance Print Sets	DEC STD 117	
Hardware Manual	DEC STD 003	

Subject	Reference	Subhead or other (as indicated)
Documentation (cont'd)		
Incoming Area Operating	DEC STD 059-3	
Incoming Inspection -		
Metal Fabrication	DEC STD 059-2	
PAVES	DEC STD 059-1	
Plastics	DEC STD 059-2	
Integrated Circuit Test		
System Control	DEC STD 133	
Legal Guidelines	DEC STD 197	
Magnetic File Structure	DEC STD 149	
Magnetic Tape Labels	DEC STD 149	
Microfilm Aperture Cards	DEC STD 033	
Module	DEC STD 140	
Package System	DEC STD 126	
Process	ELMF308-00	s 1.4
Programmable Devices	DEC STD 184	
Purchase Specifications	DEC STD 055	
ROM/PROM	DEC STD 184	
Symbology Standard	DEC STD 165	
Wirewrap Backplane Release	DEC STD 181	
Documenting Systems Messages	DEC STD 170	
Document		
Class Codes, Drawing Numbers	DEC STD 012-2	
Parts Lists	DEC STD 025-0	s 3.1
Mechanically Typed	DEC STD 182	s 2.10
Document-Number		
Automated Parts List	DEC STD 025-2	s 2.1.3
Identification Conventions	DEC STD 012-0	
KPL Input	ELENKPL-UG	s 2.1.2
Naming Conventions	DEC STD 006	
Parts Lists	DEC STD 025-0	s 3.1,3.2
Documentation Practice,		
Brazing	ANSI/AWS A2.4 - 1979	
Dimensioning and Tolerancing	ANSI Y14.5 - 1973	
Forgings	ASA Y14.9 - 1958	
Gear and Hypoid Drawing	ANSI Y14.7.2 - 1978	
Gear Drawing	ANSI Y14.7.1 - 1971	
Multi and Sectional View Drawings	ANSI Y14.3 - 1975	
Non-Destructive Testing Symbols	ANSI/AWS A2.4 - 1979	
Pictorial Drawing	ASA Y14.4 - 1975	
Screw Thread Representation	ANSI Y14.6 - 1978	
Welding Symbols	ANSI/AWS A2.4 - 1979	
Document Requirements Checklist,		
Mechanical	DEC STD 010-1	
Printed Circuit Design	DEC STD 010-2	
Double		
Eyelet Machine	ELMF308-04	s 4.1
Helical Format, Gear Drawing	ANSI Y14.7.1 - 1971	

Subject	Reference	Subhead or other (as indicated)
Double (Cont.)		
Module	DEC STD 030	figure 12
Sided PTH, Backpanel	DEC STD 030	s 8
DP01-A Cable Assembly	7665032-00	
Drafting Manual-Volume 1 of,		
Bevel and Hypoid Gears	ANSI Y14.7.2 - 1978	
Casting	DEC STD 020	
Checking	DEC STD 019	
Decimal Dimensions	DEC STD 019	
Dimensioning and Tolerancing	ANSI Y14.5 - 1973	
Drawing Directories	DEC STD 024	
Engineering Document Acceptance	DEC STD 182	
Finish and Color	DEC STD 092	
Forgings	ASA Y14.9 - 1958	
Manual (Itself)	ELENGRS-D1	
Multi and Sectional View Drawings	ANSI Y14.3 - 1975	
Parts Lists	DEC STD 025	
Pictorial Drawings	ANSI Y14.4 - 1957	
Powder Metal Bearings and Bushings	DEC STD 179-1	
Powder metal Structural Parts	DEC STD 179-2	
Purchase Specifications	DEC STD 055	
Screw Thread Representation	ANSI Y14.6 - 1978	
Sizes and Format for Engineering Drawings	DEC STD 013	
Spur, Helical, Double Helical, and Rack Gears	ANSI Y14.7.1 - 1971	
Symbols For Welding and Non-destructive Testing	ANSI/AWS A2.4 - 1979	
Workmanship	DEC STD 116	
Drawing,		
Blocks	DEC STD 013	s 4
Definitions	DEC STD 013	s 1
Engineering Formats	DEC STD 013	s 3
Multi and Sectional View	ANSI Y14.3 - 1975	
Recreated	DEC STD 182	s 2.9
Size and Format Requirements	DEC STD 182	s 2.2
Sizes	DEC STD 013	s 2
Drawing		
Directory Requirements	DEC STD 024	
Number, DD	DEC STD 024-0	s 2.1
Size, DD	DEC STD 024-0	s 2.2
Drawings reference for PC Design	DEC STD 030	table 2
DRB 106A Format, DD	DEC STD 024-0	s 2.3
DRB 107 Format, DD	DEC STD 024-0	s 2.4
DRB 108 Format, DD	DEC STD 024-0	s 2.5
DRB 126A Format, DD	DEC STD 024-1	s 2.1
Dual Dimensioning	ANSI Y14.5 - 1973	s 5-7

Subject	Reference	Subhead or other (as indicated)
Dual In-Line Packages (DIPS)		
On Modules	DEC STD 030	table 10, 11
Insertion Codes		
- .300 inch centers	7665228-00	s 8
- .400 inch centers	7665228-00	s 9
- .600 inch centers	7665228-00	s 10
Lead Trimmer	ELMF308-01	s 2.2

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Subject	Reference	Subhead or other (as indicated)
Early Warning System (EWS), Master Parts File Field	DEC STD 137	Table 1
ECO		
And Retrofit	ELMF308-02	s 3
Notation, Parts Lists	DEC STD 025-1	s 2.6
Status Sheet	7665077-00	
Edit, Automated Parts Lists	ELENKPL-UG	s 3.0
Editing, Hardware and Software	DEC STD 147	
Effect of Metal Capacitance, Gate Array Design	ELMP400-UG	s 4.7
EIA RS-232C, Binary Interfaces	DEC STD 053	
EIC (Equivalent ICs)	DEC STD 030	table 4, rule 2020
Electrical		
Characteristics, Gate Array	ELMP400-UG	s 2.4
Interconnections, Symbology	DEC STD 056-4	
Mechanical Components, Symbology	DEC STD 056-3	
Shock Hazards	7665120-00	
Electroglas Water Prober		
S3260 Test Specification	7665275-00	
1034 Prober, Operating Instructions	7665276-00	
Electrostatic Sensitive Devices, Handling	7665067-00	
Elevation, Components from board	DEC STD 030	rule 6040
EMI/Electromagnetic Interface	DEC STD 102-7	
Engraved Line Colonny	ELMF308-04	s 3.2.6
Empty Component Reels	ELMF308-01	s 3.5.3
Emulsion Protection	7665178-00	
End Tails, Wirewrap-Workmanship Criteria	DEC STD 116-6	s 7.0
Engineering	DEC STD 100	
Change Order, ECO Status Sheets	7665077-00	
Main DEC Change Order	7665195-00 (obsolete)	

Subject	Reference	Subhead or other (as indicated)
Engineering (cont'd)		
Purchase Specification	DEC STD 100	
Committee, DEC STD	DEC STD 001-1	
Document Acceptance Criteria, Requirements	DEC STD 182	s 2.0
Documentation, Archiving Microcode	DEC STD 183	
Backplane	DEC STD 193	
Computer Media Identification	DEC STD 185	
Dimensioning And Tolerancing	DEC STD 114	
Magnetic Media	DEC STD 185	
Microcode	DEC STD 183	
Programmable Devices	DEC STD 184	
PROM's	DEC STD 184	
SUDS Documentation	DEC STD 194	
Unigraphics Documentation	DEC STD 195	
Engineering Information and Documentation Standards,		
Abbreviations and Unit of Measurements	DEC STD 015	
Archiving Engineering Information	DEC STD 188	
Archiving Microcode	DEC STD 183	
Backplane Documentation	DEC STD 193	
Cable and Harness Documentation	DEC STD 022	
Casting Standard	DEC STD 020	
Computer Special Systems Numbering	DEC STD 012-6	
Confidential Engineering Information and Documentation	DEC STD 128	
Decimal Dimensioning	DEC STD 114-1	
Document Acceptance	DEC STD 182	
Drawing Directories	DEC STD 024	
Engineering Documentation Checking	DEC STD 010-0	
Engineering Notebooks	DEC STD 141	
Field Service Part Numbering	DEC STD 012-8	
Hybrid Assembly Documentation	DEC STD 026	
Inventory Class Codes - Document and Part	DEC STD 012-2	
Legal Guidelines for Digital Publications	DEC STD 197	
Logic Symbology - Circuit Schematics	DEC STD 056	
Low Volume PC Board Process	DEC STD 142-2	
LSI/VLSI Documentation	DEC STD 027	
Manufacturing Plant Documentation	DEC STD 115	
Magnetic Media	DEC STD 185	
Manufacturing Control Part Numbering	DEC STD 012-5	
Master Parts File	DEC STD 137	
Metric Dimensioning	DEC STD 114-2	

Subject	Reference	Subhead or other (as indicated)
Microfilm Aperture Cards	DEC STD 033-0,-1,-2	
Mnemonic Drawing Codes	DEC STD 012-1	
Module Documentation Structure	DEC STD 140	
Packaged Systems Documentation	DEC STD 126	
Packaged System Identification	DEC STD 012-3	
Unified Numbering Code - Part and Document Identification Conventions	DEC STD 012-0	
Part and Document Naming	DEC STD 006	
Part List	DEC STD 025	
Printed Circuit Release	DEC STD 142-0	
Programmable Devices Documentation	DEC STD 184	
Revisions on Engineering Drawings	DEC STD 014	
Sizes and Formats for Engineering Drawings	DEC STD 013	
Software Box Requirements	DEC STD 129	
Software Distribution Center	DEC STD 012-4	
SUDS Documentation	DEC STD 194	
Unigraphics Documentation	DEC STD 195	
Wirewrap Modules/Backplanes	DEC STD 181	
74-Class Part Numbering	DEC STD 012-7	
Engineering		
Information Control, Archive Submission	DEC STD 188	
Notebooks, Policy and Requirements	DEC STD 141	
Engineering Specifications		
Format and Index	7665000-00 (obsolete)	
Format Procedure	7665287-00	
Index 7665 Specifications	ELINDEX-00	
Environmental Capabilities, Paints and Finishes	DEC STD 092	s 3.0
Environmental Requirements	DEC STD 102	
EN-01008B-R675(491) PNRF	DEC STD 055	figure 1
EN-01460-03 Rev A, ECO Status Sheet	7665077-00	
EN-01548-03 REV A, CAR Form	7665069-00	
EPLS,		
KPL to	ELENKPL-UG	s 13.3
Field Definition for MPF	DEC STD 137	
Equalize Distribution of Copper	DEC STD 030	rule 5292
Error Logging, System Description	DEC STD 153	
Escape Sequence		
Registration	DEC STD 138	
Standard	DEC STD 110	
Etch Cuts, Documentation	DEC STD 140-1	
Etched copper plane, design considerations	DEC STD 030	rule 5292
Expansion Pin	ELMF308-01	s 3.7.3

Subject	Reference	Subhead or other (as indicated)
Experimental, Printed Circuit		
Prototype	DEC STD 142-1	s 2, 5.2.1
Exploded Views, Pictorial Drawings	ASA Y14.4 - 1957	s 4-13
Export Controls, US Govt.	DEC STD 198	
Exposed Copper, Touchup Requirement	7665010-00	s 2.7
Extension of Connector Fingers	DEC STD 030	figure 19,rule 5020 5040, 5050, 5060
External Connectors, Backplanes	DEC STD 030	rule 8140
Eyelet Insertion	ELMF308-01	s 3.1.1
Eyelet Machine,		
Double	ELMF308-04	s 4.1
Feed Through	ELMF308-01	s 3.2
Split Lug	ELMF308-01	s 3.3
Eyelets, Rolled Flanged - Workmanship		
Criteria	DEC STD 116-5	s 6.0
Eyeletting Machine, clearance		
required	DEC STD 030	figure 34,rule 6020
Eyeletting Press-Air Mite	ELMF308-04	s 4.2
Eyewash Unit	ELMF308-00	Table 1

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Subject	Reference	Subhead or other (as indicated)
Fabrication		
Considerations, Checking	DEC STD 010	s 1.10
Final IC	ELMP400-UG	s 1.4
Process, Gate Array		
Shops.	7665060-00	
Fan Tester	7665100-00	
Faston Tabs, backplanes	DEC STD 030	rule 8150
FCC Labelling,		
Compliance	DEC STD 103-1	
Labeling Requirements	DEC STD 103-1	
Non-Compliance	DEC STD 103-1A	
Non-Verification Labelling	DEC STD 103-1A	
Product Status List	DEC STD 103-1	s 1.4.2
Regulations, Labelling	DEC STD 103	
Features, Required within PC outline	DEC STD 030	s 5.1
Feed-throughs,		
On grid	DEC STD 030	
Spacing	DEC STD 030	rule 5130,5140
Standard Grid	DEC STD 030	s 5.3.2, rule 5120

Subject	Reference	Subhead or other (as indicated)
Field		
Definitions, Master Parts File	DEC STD 137	
Drawing	DEC STD 010	s 8.0
Length Specifications, Automated Parts List	DEC STD 025-2	s 4.0
Maintenance Print Sets	DEC STD 117	
Field Service,		
In-house Acceptance	DEC STD 106	
Installation Quality, Product Waivers	DEC STD 005-0,-1,-2,-3	
Part Numbering	DEC STD 012-8	
FICS (Fingerless Circuit Standards)		
Circuit Detail Requirements	DEC STD 030	figure 13,rule 2021
Outlines	DEC STD 030	figure 11, 13
Standard Process Overview	DEC STD 030	figure 8
Field		
Definitions, Master Part File	DEC STD 137	s 2
Modified Modules, Customer Return Inspection Criteria	DEC STD 264	s 4.4
Return Eligibility Criteria	DEC STD 264	s 2.1
File Name Format,		
APPLICON	ELEN302-00	s 6.7
CALDEC Library	ELEN302-00	s 3.7
GEMS Library	ELEN302-00	s 2.7
Standard Features	ELEN302-00	s 5.4.7
SUDS Library	ELEN302-00	s 4.7
Fillets and Rounds, Pictorial Drawing	ASA Y14.4 - 1957	s 4-7
Filtration Unit - Smog Hog	ELMF308-03	s 2.4
Final Assembly		
Area	ELMF308-04	s 2
Area Floor Layout	ELMF308-04	figure 1
Hand Soldering Recommendations	ELMF308-03	s 3.3
Find Number, DD	DEC STD 024-0	s 2.5.1
Fine Line 90° bends	DEC STD 030	rule 5185
Finger		
Assignments, spare	DEC STD 030	rule 5040
Assignments, Standard	DEC STD 030	rule 5020
Circuit Sizes, 0.125-inch	DEC STD 030	figure 12
Clips - Titanium	ELMF308-03	s 2.3.3, 2.3.5
Contact Gage	ELMF308-02	s 2.1
Designations	DEC STD 030	rule 5042
Restricted	DEC STD 030	rule 5030
Spare	DEC STD 030	rule 5040
Fingerless		
Circuits, standard size	DEC STD 030	figure 11
Modules, Standard	DEC STD 030	figure 11, 13

Subject	Reference	Subhead or other (as indicated)
Fingers Deletion of Unnecessary	DEC STD 030	ule 5044
Finish		
And Color Standard	DEC STD 092	
Pictorial Drawings	ASA Y14.4 - 1957	s 4-11
QC Procedure	7665019-00	
Finished		
Board Size, Backplane	DEC STD 030	rule 8000
Circuit Hole and Pad sizes	DEC STD 030	rule 5190
Holes Larger than 0.055 inch	DEC STD 030	rule 5235
Hole Size, Multilayer Boards	DEC STD 030	rule 5285
Finishing Guidelines, Paints and Finishes	DEC STD 092	s 5.0
Finish Specifications,		
Conversion and Oxide Coating	DEC STD 092-3	
Metal Plating	DEC STD 092-2	
Paints	DEC STD 092-1	
First choice, Auto-inserted axial components	DEC STD 030	rule 4030
Fixed Head .01 Capacitor Insertion Machine	ELMF308-01	s 3.7
Fixed Software Box	DEC STD 129	s 2.1.1
Fixtures, Fabrication - Control	7665060-00	
Flame Test		
Resistor Flameproof Test	7665253-00	
Test Requirements	7665257-00 (obsolete)	
Non-metallic Material	7665288-00 (obsolete)	
Flammability	7665264-00	
Flexible Cable, Workmanship Criteria	DEC STD 116-2	s 10.0
	DEC STD 116-4	s 13.0
Flip Chip System, Standard Vibration Test	7665057-00	
Floppy Disk,		
Data Interchange	DEC STD 154 (obsolete)	
Identification Across Systems	DEC STD 154 (obsolete)	
Flux, Chemical Safety Data	ELMF308-03	s 2.3.8.1
Flux Dispenser - Touch Up Area	ELMF308-03	s 3.2
Flux Hydrometer	ELMF308-03	s 2.3.3
Flux-kenco	ELMF308-03	s 2.3.3
Flux Safety Data	ELMF308-03	s 2.3.6
Flux Thinner	ELMF308-03	s 2.3.3, 2.3.6
Flux Thinner Safety Data	ELMF308-03	s 2.3.6
Foil Leaf Imprinter	ELMF308-04	s 3.1
Foreign Software Manuals, Legal Notices	DEC STD 172	s 2.3
Forgings, Documentation Practice	ASA Y14.9 - 1958	
Format,		
Checking	DEC STD 010	s 7.0
DEC Std	DEC STD 001-2	

Subject	Reference	Subhead or other (as indicated)
Engineering Drawings	DEC STD 013	
Extended Matrix Parts Lists	DEC STD 025-0	s 2.3.2
Floppy Disk Volume Identification	DEC STD 154	
Hardware Manual	DEC STD 003	
Manuals-Typeset Media	DEC STD 124	
Module Parts List	DEC STD 025-0	s 2.3.1
Microfilm Aperture Cards	DEC STD 033-1	
Microform Requirements	DEC STD 162	
Punched Card	DEC STD 151	
Purchase Specifications	DEC STD 055	
Standard Preprinted	DEC STD 013	s 6
Test Procedure - Power Supply	7665024-00	
Volume Identification of Diskpacks	DEC STD 167	
Foward Recovery Testing of Diodes	7665064-00	
Functional Class Descriptor (FCD),		
Master Part File Field	DEC STD 137	Table 1
Fuses, preferred auto-inserted axial	DEC STD 030	rule 4030

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Subject	Reference	Subhead or other (as indicated)
Gage		
Finger Contact	ELMF308-02	s 2.1
Module Width	ELMF308-04	s 2.5.4
Gardner Denver,		
Maximum Wrap Area	DEC STD 030	rule 8310
Wirewrap Routing	7665013-00	
Gate Array,		
CAD Tool Verification	ELMP400-UG	s 5.2
Cell Configurations	ELMP400-UG	s 2.1
Cell Layout	ELMP400-UG	figure 2-1
Logic and Layout Analysis Tools	ELMP400-UG	s 1.3.1
Gate Array Design,		
Configuration Rules	ELMP400-UG	s 3.2
DC Loading and Restrictions	ELMP400-UG	s 3.1
Effect of Metal Capacitance	ELMP400-UG	s 4.7
Electrical Characteristics	ELMP400-UG	s 2.4
Layout Synthesis Tools	ELMP400-UG	s 1.3.2
Manual	ELMP400-UG	
Packaging Configuration	ELMP400-UG	s 7.1
Process Summary	ELMP400-UG	Appendix B
Test Patterns	ELMP400-UG	s 6.3
Test Pattern Generation	ELMP400-UG	s 6.1

Subject	Reference	Subhead or other (as indicated)
Test Program Generation Tools	ELMP400-UG	s 1.3.3, 6.2
Testability Guidelines	ELMP400-UG	Appendix A2
Transition Delays	ELMP400-UG	s 4.1
Verification Process	ELMP400-UG	s 5.1
Gate Array Fabrication,		
Final IC	ELMP400-UG	s 1.4
Wafer Test	ELMP400-UG	s 1.4.2
Gauge Calibration,		
Depth Micrometer	7665055-00 (obsolete)	
Dial and Test Indicator	7665058-00 (obsolete)	
Dial Push/Pull	7665048-00 (obsolete)	
Dial Vernier	7665053-00 (obsolete)	
Vernier Caliper	7665054-00 (obsolete)	
Gauges, Module Inspection	7665042-00	
Gear		
Drawing, Documentation Practice	ANSI Y14.7.1 - 1971	
And Hypoid Drawing, Documentation Practice	ANSI Y14.7.2 - 1978	
Nomenclature	ANSI Y14.7.1 - 1971	s 7-6
GEMS Library,		
File Name Format	ELEN302-00	s 2.7
General Description	ELEN302-00	s 2
General Hand Soldering Recommendations	ELMF308-03	s 3.3
General Producibility Requirements	DEC STD 030	s 2
General Radio,		
1792A Module Tester	- 7665224-00	
1792A Acceptance Procedure	- 7665224-01	
Module Test Program Request	- 7665224-03	
Module Program Generation	- 7665224-04	
1792A Start-up and Operation	- 7665224-05	
CAPS Message Interpretation	- 7665224-06	
1792A Preventative Maintenance-	7665224-08	
Release Procedure-CAPS Diagnostics	- 7665224-09	
Glossary,		
Digital Product Safety	DEC STD 119-3	
Logic Symbology	DEC STD 056-6	
Printed Wiring Terminology	DEC STD 016	
Gloves - Soldering	ELMF308-03	s 2.3.3
Gold Conservation,		
Connector Pins	DEC STD 030	rule 4020
Deletion of Fingers	DEC STD 030	rule 5044
Gold Contact		
Cleaning Process	7665266-00	
Workmanship Criterion	7665051-00	
Alignment-Inspection Procedure	7665002-00	

Subject	Reference	Subhead or other (as indicated)
Gold-Plated		
Areas, Routing Conductors	DEC STD 030	rule 5060
Conductors Conservation	DEC STD 030	rule 5044
Gold Plating Process Specification for Contacts	7665055-00	
Grieve Baking oven	ELMF308-03	s 2.1.1, 2.2
Griplet Machine	ELMF308-01	s 3.8
Griplets	DEC STD 116-1	s 8.0
G022 Cable Tester, Test Procedure	7665018-00	
G615, Inspection Procedure	7665011-00	
Ground/Power Plan,		
Backplane Twisted Pairs connections	DEC STD 030	rule 8360
Press-pin backplanes	DEC STD 030	rule 8570
Negative Plotted	DEC STD 030	rule 5310
Selection, Wirewrap Twisted Pair	DEC STD 030	rule 8360

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Subject	Reference	Subhead or other (as indicated)
H Master Zero, Relation to Edge of Circuit	DEC STD 030	figure 30
	DEC STD 140	
Hand Assembly		
Aids	ELMF308-02	s 2.4
Pass Down Line	ELMF308-02	figure 1
Tools	ELMF308-02	s 2.2
Work Benches	ELMF308-02	s 2.3
Hand Shear		
Hex	ELMF308-04	s 2.3
Hydraulic	ELMF308-04	s 2.6
6 inch	ELMF308-04	s 2.4
24 inch	ELMF308-04	s 2.5
Hand Soldering Recommendations	ELMF308-03	s 3.3
Handle		
Holes	DEC STD 030	rule 5190
Metal	DEC STD 030	figure 12
Plastic	DEC STD 030	figure 12
Plastic, routing under	DEC STD 030	rule 6070
Stamping Machine - Metal	ELMF308-04	s 3.2
Stamping Machine - Plastic	ELMF308-04	s 3.1
Hardware Design Assurance Standards,	7665099-00	
AC Power Line Standard	DEC STD 122	

Subject	Reference	Subhead or other (as indicated)
Hardware Design Assurance Standards (cont'd)		
AC Power Wiring, etc.	DEC STD 002	
Chemical and Corrosive Environmental Classifications	DEC STD 109	
Circuit Design Guidelines	DEC STD 004	
Cooling	DEC STD 120	
Design and Certification of Hardware Products to National and International Regulations and Standards	DEC STD 060	
Design Product Safety	DEC STD 119	
Electrical Requirements for Binary Interfaces that conform to EIA RS-232-C or CCITT V.28	DEC STD 053	
EMI/Electromagnetic Interface	DEC STD 102-7	
Environmental Standard for Computers and Peripherals	DEC STD 102	
Export Controls	DEC STD 198	
FCC Labelling	DEC STD 103	
Operational Requirements for Serial Terminals and System Interfaces Operating as DTEs Connected to EIA RS-232-C or CCITT V.28 Point-to-Point Modems	DEC STD 052	
Power Control Bus Standard	DEC STD 123	
Product Acoustic Noise Acceptability	DEC STD 104	
Product Waivers	DEC STD 005-0	
Reliability Prediction	DEC STD 139	
Signal Integrity	DEC STD 186	
US Govt. Export Controls and Licensing	DEC STD 198	
Hardware Engineering		
AC Power Line Requirements	DEC STD 122	
AC Power Wiring and Receptacles	DEC STD 002	
Circuit Design Guidelines	DEC STD 004	
Disk Format	DEC STD 144	
Environmental Requirements	DEC STD 102	
International Regulations	DEC STD 060	
Logic Symbology	DEC STD 056	
LSI Bus Specification	DEC STD 160	
Manual, Requirements	DEC STD 003	
Massbus Interface Specification	DEC STD 159	
Omnibus Specification	DEC STD 157	
Power Control Bus	DEC STD 123	
Printed Circuit Release	DEC STD 142	
Product Safety	DEC STD 119	
Signal Integrity	DEC STD 186	

Subject	Reference	Subhead or other (as indicated)
Hardware Engineering (cont'd)		
Support, Backplanes	DEC STD 030	s 8
Unibus Specification	DEC STD 158	
Variations, DD	DEC STD 024-1	s 2.4
Hardware Engineering Design,		
Cooling	DEC STD 120	
Diagnostics	DEC STD 148	
Dimensioning and Tolerancing	DEC STD 114-1	
Environmental Requirements	DEC STD 102	
Escape Sequence	DEC STD 110	
Packaged Systems	DEC STD 126	
PDP-11 Extended Instructions	DEC STD 168	
Product Safety	DEC STD 119	
Punched Card Format	DEC STD 151	
Standard Coded Character Set	DEC STD 051	
Terminal Keyboard	DEC STD 107	
Terminal Synchronization	DEC STD 111	
VAX Architecture	DEC STD 032	
Harness Fabrication	DEC STD 116-4	s 5.0
Health Hazard Data,		
Flux	ELMF308-03	s 2.3.8.1
Oils	ELMF308-03	s 2.3.8.3
Thinners	ELMF308-03	s 2.3.8.2
Heat Relief Pads	DEC STD 030	figure 28,rule 5280
Helical Format, Gear Drawing	ANSI Y14.7.1 - 1971	s 7-5
Hermetic Seals	DEC STD 116-1	s 28.0
Hex		
Board Definition	DEC STD 030	figure 12
Board Trimming Shear	ELMF308-04	s 2.3
High Density,		
Module Outlines and EIC	DEC STD 030	table 4
Pad Sizes	DEC STD 030	table 14
Unit Cost	DEC STD 030	table 5
Hold-down Mounting Holes, Backplanes	DEC STD 030	rule 8440
Hole,		
Common Components Sizes	DEC STD 030	rule 5190
Finished	DEC STD 030	rule 5190
Handle	DEC STD 030	rule 5190
Inspection-Plated Thru Hole Panels	7665009-00	s 3.0
Power Supply - Inspection Criteria	7665026-00	
Size standard for PCB's	7665007-00	
Tooling/Testing, Backplane	DEC STD 030	rule 8550
Hole/pad size, standard selections	DEC STD 030	rule 5190
Hollis Wave Solder Machine	ELMF308-03	s 2.3
Hooks - Spring for DIP Machine	ELMF308-01	s 3.4.3
Hydraulic Power Shear	ELMF308-04	s 2.6
Hydrometer - Flux	ELMF308-03	s 2.3.3

Subject	Reference	Subhead or other (as indicated)

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Subject	Reference	Subhead or other (as indicated)
IC (Integrated Circuit)		
Bin Assembly	ELMF308-01	s 3.4.2
Plug Puller	ELMF308-01	s 3.4.2
Stick	ELMF308-01	s 3.4.2
ICMAST Table, Insertion Categories	7665228-00	s 3.4
IDEAS,		
Gate Array Design	ELMP400-UG	s 1.3.1.3
Library, General Description	ELEN302-00	s 5.1
Identification, Finished Cable Assembly	7665045-00	
Identification Label - Sequence Reel	ELMF308-01	s 3.5.3
Incandescent Lamps	7665251-00	
Incoming Inspection,		
AC Parameter Test	7665357-00	
Date Coding Material (with colors)	7665064-00	
DEC AICT A-D Calibration	7665063-00	
DEC AICT Set-up	7665062-00	
Diode Forward Recovery Test Set-up	7665065-00	
Metals and Plastics Documentation	DEC STD 059-2	
MOS Handling	7665067-00	
Operating Procedure		
PAVES	DEC STD 059-1	
Standard Operations Procedure-Plant	DEC STD 059-3	
Water Bath Thermal Shock Oven	7665066-00	
Indexes, Software Manual	DEC STD 118	
Information Interchange, Character Sets	DEC STD 051	
Data Values in ASCII character Strings	DEC STD 145	
In-house Acceptance,		
Procedure Standard	DEC STD 106	
Inner Layer		
Clearance	DEC STD 030	table 16, rule 5200
Conductor Relief	DEC STD 030	figure 27, rule 5230
Holes Press Pin Backplane	DEC STD 030	rule 8560
INSCODE Table, Legitimate Insertion Codes	7665228	s 3.3

Subject	Reference	Subhead or other (as indicated)
Insertability Code,		
Determining	7665228-00	s 2.4
Master Part File Field	DEC STD 137	table 1
Problem Sheet	7665228-00	figure 1
Insertion		
Area	ELMF308-01	s 3.1
Room Floor Layout	ELMF308-01	figure 4
Spacing and Directions	DEC STD 030	figure 32
Template, Press-pin Backplanes	DEC STD 030	rule 8580
Inspection		
Automatic - Zehntel	ELMF308-05	s 2.2
Criteria, Contact Appearance or PCB	7665051-00	
Gage - Component Height	ELMF308-02	s 2.1
Manufacturing Operations Plan	DEC STD 101	
Plotted Master Artwork	DEC STD 034	
Wirewrap Panel Procedure	7665001-00	
Inspection Procedure,		
Alignment of Gold Contacts on Circuit Boards	7665002-00	
Backpanel-8/I	7665016-00	
Field Records	DEC STD 264	
G610, G611, G612	7665011-00	
K716, Interface Block	7665003-00	
Module-Final	7665039-00	
PCB Thickness	7665008-00	
Plated Thru Hole Panels	7665009-00	
Single sided Panels	7665026-00	
Soldermask Panels	7665006-00	
Wirewrap Process	7665013-00	
Insulation, Routing Conductors Near Metal	DEC STD 030	rule 6070
Integrated Circuit,		
Continuity Test	7665269-00	
DEC IC Test System	7665160-00	
Documentation and Test Systems Systems Control	DEC STD 133	
Gate Array	ELMP400-UG	s 1.1
Package Dimensions	DEC STD 030	rule 4140, 4150
Selection Assistance	DEC STD 030	table 7
Thermal Shock	7665220-00	
Integrated Circuit,	DEC STD 116-3	s 2.5
Interconnect Verifier (IV), Gate Array Design	ELMP400-UG	s 1.3.1.5
Interconnections Between Adjacent Pads	DEC STD 030	rule 5180
Interface,		
LSI Bus	DEC STD 160	
Massbus	DEC STD 159	

Subject	Reference	Subhead or other (as indicated)
Interface, (cont'd)		
Omnibus	DEC STD 157	
Unibus	DEC STD 158	
Interfacial Holes,		
With Components	DEC STD 116-1	s 33.0
Without Component Leads	DEC STD 116-1	s 34.0
Interliner Paper - Sequencer	ELMF308-01	s 3.5.3
Internal Use Only, Labelling	DEC STD 128	
International Regulations,		
Product Certification	DEC STD 060	
Intersections, Pictorial Drawings	ASA Y14.4 - 1957	s 4-8
Inventory Class Codes,		
Part Numbers	DEC STD 012-2	
Invertory Class, parts and		
documents 50-79	DEC STD 006	
In-Plant Product Safety Hold		
Procedure	DEC STD 005-6	
Iron		
Castings, Tolerances	DEC STD 020	
Phosphate on Cold Roll Steel	7665171-00	
Desoldering	ELMF308-04	s 2.7.4
Rework and Repair	ELMF308-04	s 2.7.2
Soldering	ELMF308-03	s 3.3
Irridite Finish, Touch-up	7665022-00	

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Subject	Reference	Subhead or other (as indicated)
Kenco		
Flux	ELMF308-03	s 2.3.3, 2.3.6
Oil	ELMF308-03	s 2.3.3, 2.3.6
Thinner	ELMF308-03	s 2.3.3, 2.3.6
Keyboards,		
Customer Return Inspection Criteria	DEC STD 264	s 4.1
Terminal	DEC STD 107	
Keynames, Software Documentation	DEC STD 165	
Key pin designations	DEC STD 030	rule 6060
KPL User Info	ELENKPL-UG	
K716 Interface Block-		
Inspection Procedure	7665003-00	

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Subject	Reference	Subhead or other (as indicated)
L-code Machine Inserted Components	DEC STD 030	Table 9
	7665228-00	rule 4031
"L" Number Assignment, CALDEC Library	ELEN302-00	s 3.1
Labelled Files, Cassette Format	DEC STD 125	
Labels, Current Logic Function	DEC STD 056-7	
Labor Standards - Setting for Module Assembly & Test	ELMF308-00	s 1.4.5
Lacquer - Stik Red	ELMF308-04	s 3.2.6
Layer,		
Identification	DEC STD 030	rule 5015
Standard Technology	DEC STD 030	figure 9
Layout,		
Capacitors	DEC STD 030	rule 6120
Component Lead holes and Feed Throughs	DEC STD 030	rule 5070
Structure	DEC STD 030	figure 10
Standard Grid	DEC STD 030	rule 5070
Synthesis Tools, Gate Array Design	ELMP400-UG	s 1.3.2
Lead Clipping and Touch-up Area Floor Layout	ELMF308-03	s 2.7.2
Lead,		
Machine Routed	DEC STD 116-1	s 25.0
Peel Back	DEC STD 116-1	s 42.0
Legal		
Guidelines, Digital Publications	DEC STD 197	
Notices, Licensed Software Sources	DEC STD 172	
Publications	DEC STD 197	
Software Manuals	DEC STD 172	
Legitimate Insertion Codes	7665228-00	s 3.3
Lettering,		
Guide	DEC STD 182	table 4
Microfont	DEC STD 182	s 2.4.1
Title Block	DEC STD 182	table 2, 3
Level Of Acceptability,		
Customer Returns	DEC STD 264	s 2.2.1
Workmanship	DEC STD 116-1	
Levels, Wirewrap	DEC STD 030	rule 8530
Liability Protection, Guidelines for Publications	DEC STD 197	
Library,		
Applicon-General Description	ELEN302-00	s 6.1

Subject	Reference	Subhead or other (as indicated)
Library (cont'd)		
CALDEC - General Description	ELEN302-00	S 3.1
GEMS - General Description	ELEN302-00	s 2.1
IDEAS - General Description	ELEN302-00	s 5.1
Microfile Reference	DEC STD 033-2	
Special Features	ELEN302-00	s 7.1
SUDS - General Description	ELEN302-00	s 4.1
Unigraphics	ELEN302-00	s 8.1
Licensed Software Sources, Legal Notices	DEC STD 172	s 2.1
Line		
Printer Output, High Speed	DEC STD 182	s 2.10.5
Quality	DEC STD 182	s 2.5
Weights, Pictorial Drawings	ASA Y14.4 - 1957	s 4-4
Width Fine Line	DEC STD 030	figure 25
Width/Spacing	DEC STD 030	figure 25
Width/Spacing, press-pin Backplanes	DEC STD 030	rule 8540
Width/Spacing, Wave-Soldered Backplanes	DEC STD 030	rule 8400
Lines, Lead Pencil	DEC STD 182	s 2.5.1, s 2.5.2
Loading Analysis Rules, Gate Array Design	ELMP400-UG	s 3.1
Logic		
Design, Gate Array	ELMP400-UG	Appendix B-2
Diagrams, Symbology	DEC STD 056	
Layout Analysis Tools, Gate Array Design	ELMP400-UG	s 1.3.1
Symbology	DEC STD 056	
Logo, Location on Printed Circuit Outline	DEC STD 030	table 13
Loose		
Component Taping Machine	ELMF308-01	s 2.4
DIP Insertion Machine - c/c	ELMF308-01	s 3.4
Low-Pass Filter Capacitors	DEC STD 030	rule 6130
LSI		
Bus, Specification	DEC STD 160	
Documentation, Requirements	DEC STD 027	

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Subject	Reference	Subhead or other (as indicated)
Machine Insertable		
Components Codes .200 Inch Pitch	7665228	s 2.1
Components, Preferred for PC Design	DEC STD 030	rule 4030
Parts	DEC STD 030	rule 4031
Machine Insertion		
Axial Components	DEC STD 030	rule 4030
Room Floor Layout	ELMF308-01	figure 4, 6
Machine		
File Structure Standard	DEC STD 149	
Large - Bodied Axial Components	7665228	s 7.2
Language, VAX Architecture	DEC STD 032	
Maintenance, Tools Required	ELMF308-00	s 5, table 3
Media, Documentation Requirements	DEC STD 185	
Performance Data Collection	7665278-00	
Setups, Standard Axial Component Insertion	7665228-00	s 6.2
Standard Axial Components	7665228-00	s 6.2
SUDS	DEC STD 194	
UNIGRAPHICS	DEC STD 195	
Magnetic Tape		
Cleaning/Testing	7665184-00	
Error Recovery	DEC STD 174	
Label Standard	DEC STD 149	
Maintenance Operation Protocol	DEC STD 191	
Major Supplier Stockroom (MSS), Master Part File Field	DEC STD 137	table 1
Make VS. Buy Code, Master Part File Field	DEC STD 137	table 1
Manila Tape Folders	ELMF308-01	s 3.4.2, 3.5.2
Manuals,		
Documentation Symbology	DEC STD 165	
Documenting Systems Messages	DEC STD 170	
Field Maintenance Print Set	DEC STD 117	
Formats for Front and Back Pages	DEC STD 146	
Format for Typeset	DEC STD 124	
Hardware-Standard	DEC STD 003	
Hardware/Software-Updating	DEC STD 143	
Legal Guidelines	DEC STD 197	
Legal Notices for Software	DEC STD 172	
Software-Appendices	DEC STD 118	
Software-Indexes	DEC STD 118	

Subject	Reference	Subhead or other (as indicated)
Manuals, (cont'd)		
Software-Section Numbering	DEC STD 118	
Manufacturability Rating	DEC STD 030	figure 6
Manufacturing,		
Backplane Release Requirements	DEC STD 181	
Compability, Standard Circuit	DEC STD 030	table 4
Control Part Numbering	DEC STD 012-5	
DP01-A Cable Assy	7665032-00	
Finished Cable Assembly Identification	7665045-00 (obsolete)	
Module Process Steps	DEC STD 030	figure 7
Module-Standard	DEC STD 030	
Module Release Requirements	DEC STD 142	
Motor Balancing	7665020-00	
Operations Plan	DEC STD 101	
Part Numbers	DEC STD 012-5	
Plant Capacity Model	ELMF308-00	s 4
Plant Process Documentation	DEC STD 115	
Supplier Product Line (MSP) Master Part File Field	DEC STD 137	table 1
Mark V Component Lead Former	ELMF308-01	s 2.1.2
Mark IX Lead Trimmer	ELMF308-01	s 2.2.1
Marked Modules, Customer Return Inspection Criteria	DEC STD 264	s 4.5
Marking,		
Location Table	DEC STD 030	table 13
Mechanical Parts	DEC STD 178	
Modules without Handles	7665029-00	
70-and 74-Class Parts	DEC STD 178	
Massbus Interface Specification	DEC STD 159	
Master Parts File, Field Definitions	DEC STD 137	s 2
Material Repair Organizations	DEC STD 264	s 1.3.1
Math Symbols	DEC STD 116-8	s 8.0
Maturity Test,		
Design	7665268-00	
Process	7665268-00	
Maximum Wirewrap Area	DEC STD 030	rule 8310
Mean Time Between Failure (MTBF)	7665180-00 (obsolete)	
Measling, PCB	DEC STD 116-1	s 6.0
Mechanical Clearances - External Layers	DEC STD 030	rule 6100,6101,6102
Mechanical		
Fabrication, Acceptance Criteria	DEC STD 187	
Fabrication, Prototype PC	DEC STD 142-1	s 2
Fastener	DEC STD 116-5	s 3.0

Subject	Reference	Subhead or other (as indicated)
Mechanical (cont'd)		
Properties, Powder Metal	DEC STD 179-2	Appendix A.1
Media,		
Cleanliness and Surface Condition	DEC STD 182	s 2.6
Physical Condition	DEC STD 182	s 2.7
Memory		
Circuit Boards	7665052-00	
Disc	7665175-00	
Stack	7665085-00	
Stack Array, Module Acceptance Criteria	7665052-00	
Mesh Pattern Heat Relief	DEC STD 030	rule 5290
Metal		
Chromate Conversion Coating	7665170-00	
Chromicoat & Irridite Finish Touchup	7665019-00	
Fabrication, Part Identifier	DEC STD 012-7	
Finish Specification	7665019-00	
Handle Stamping Machine	ELMF308-04	
Iron Phosphate on Cold Roll Steel	7665171-00	
Plating, Approved Finish Specifications	DEC STD 092-2	
Vinyl Baked Enamel Process	7665262-00	
Workmanship Standards	7665213-00	
Metric Conversion	DEC STD 116-8	s 6.0
Microcode, Archiving	DEC STD 183	
Microfiche, Typeset Manuals	DEC STD 124	
Microfilm		
Aperture Cards, Creation Process	DEC STD 033	
Distribution Process	DEC STD 033	
Format and Quality	DEC STD 033-0,-1	
Reference Library, Setup and Maintenance	DEC STD 033-2	
Requirements	DEC STD 033-1	
Special Procedures for ECO	DEC STD 182	s 2.8
Microfont, Lettering	DEC STD 182	s 2.4.1
Microforms, Format and Quality Requirements	DEC STD 162	
Micrometer, Calibration Procedure	7665043-00 (obsolete)	
Micrographics,		
Format and Quality Requirements	DEC STD 162	
Mil HBK 217B	DEC STD 139	
Mil Std 105	7665079-00 (obsolete)	
Miniature Spring Socket Driving Machine - AMP	ELMF308-01	s 3.9
Mnemonics, Signal-Schematic	DEC STD 056-4	
Mnemonic Drawing Codes, Documents	DEC STD 012-1	

Subject	Reference	Subhead or other (as indicated)
Model Acceptance,		
Power Supply Control	7665031-00	
Module,		
Assembly Process	DEC STD 030	figure 7
Assembly Process Flow Diagram	ELMF308-00	figure 1
Assembly Rules	DEC STD 030	s 6
Criteria-Memory Circuit Inspection	7665052-00	
Documentation Structure	DEC STD 140	
Flip Chip Modules Inspection	7665039-00	
Gauges, Different Types Inspection	7665042-00	
Hand Shear	7665301-00	
Identification/Marking	DEC STD 116-1	s 7.0
Identification, without Handles	7665029-00	
Inspection Flip Chip Modules	7665039-00	
Inspection Gages	7665042-00	
Machine Insertion Assembly Area	ELMF308-01	figure 4
Manufacturing Standard	DEC STD 030	
PC rules	DEC STD 030	s 5
Pre-Baking Oven - Walk in	ELMF308-03	s 2.2
Pre-Baking Small	ELMF308-03	s 2.1
Pre-Design Producibility form	DEC STD 030	figure 3
Repair	7665197-00 (obsolete)	
Repair Center, Rework Procedure	DEC STD 265	
Rework and Repair	DEC STD 255	
Test	7665155-00 7665234-00	
Thickness, Press-Pin Backplane	DEC STD 030	rule 8510
Trays - Platic	ELMF308-01	s 3.1.7
Unit Cost, Std Circuit Technology and Outlines	DEC STD 030	table 5
Width Gage	ELMF308-04	s 2.5.4
MOS		
Handling	7665067-00	
Kit - DIP Machine	ELMF308-01	s 3.4.2
Kit - Hand Assembly	ELMF308-02	s 2.4
Motor Balancing	7665020-00	
Mounting		
Bars, Backplane	DEC STD 030	rule 8120
Centers, Component	DEC STD 030	table 8,9,10,11,12
Multilayer		
Backplane	DEC STD 030	s 8
Boards, Artwork Requirements	DEC STD 030	s 5.4
Boards, Clearance Holes	DEC STD 030	figure 26
Signal Layer (MSL) Backpanel	DEC STD 030	s 8

Subject	Reference	Subhead or other (as indicated)
Multiple Wirewrap Connections	DEC STD 116-6	s 8.0
Multiview Drawing, Documentation Practice	ANSI Y14.3 - 1975	s 3-2

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Subject	Reference	Subhead or other (as indicated)
Naming Convention, Basic Gate Array Cell	ELMP400-UG	table 2-1
Naming Software Products and Releases	DEC STD 173	
NC Semi-automatic, Maximum Wrap Area	DEC STD 030	rule 8310
Negative		
Artwork Identification	DEC STD 030	rule 5016, table 13
Plotted artwork	DEC STD 030	rule 5320
Plotted ground/power planes	DEC STD 030	rule 5310
Network Services Protocol	DEC STD 190	
New		
Plant Start Up Check List	ELMF308-00	s 3, table 1
Product, design selection	DEC STD 030	figure 2
Products Purchasing, 74-Class Parts	DEC STD 012-7	s 3.1.4
Noise,		
Acoustic-Product	DEC STD 104	
Emission, Acoustic	DEC STD 104	
Nomenclature,		
Gear	ANSI Y14.7.1 - 1971	s 7-6
Gear Tooth	ANSI Y14.7.2 - 1978	s 5
Non		
Conforming Material	7665075-00	
Functional copper	DEC STD 030	rule 5296
Grid Component Holes	DEC STD 030	rule 5110
Machine Insertable parts, preferred	DEC STD 030	rule 4160
Machine Insertable Component Codes Process Compatible Components	7665228-00	s 4, 5
Metal Fabrication Part Identifier	DEC STD 012-7	s 2.1
Standard Flags, PDQ codes	DEC STD 030	figure 6
Notation Conventions, Software Documentation	DEC STD 165	
Notes,		
Automated Parts Lists	DEC STD 025-2	s 2.6
Drawing	DEC STD 010	s 1.8

Subject	Reference	Subhead or other (as indicated)
Numbering Control Systems,		
Manufacturing Plant Process	DEC STD 115	
Sequence, Discrete Components	DEC STD 030	rule 6170
Numerical Control, Dimensioning	ANSI Y14.5 - 1973	Appendix A

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Subject	Reference	Subhead or other (as indicated)
Obsolete Specification-Replacements,		
for 7665000-00	ELINDEX-00	
for 7665045-00	7665343-00	
for 7665050-00	DEC STD 116	
for 7665070-00	DEC STD 031-2	
for 7665073-00	DEC STD 059-2	
Oil,		
Chemical Safety Data	ELMF308-03	s 2.3.8.3
Safety Data	ELMF308-00	s 2.3.6
Wave Solder	ELMF308-03	s 2.3.3, 2.3.6
OLIVER, Gate Array Design	ELMP400-UG	s 1.3.1.6
Omnibus Specification	DEC STD 157	
Opcodes, PDP-11 Extended Instructions	DEC STD 168	
Operating Procedures, NC Wirewrap	7665033-00	
Operational Alert (OPAL)	DEC STD 005-5 7665298-00	
OPCOA Automatic LED Tester		
Calibration	7665074-00	
Optimum Design vs Manufacturing		
Process	DEC STD 030	figure 7
Options, Customer Return Inspection		
Criteria	DEC STD 264	s 4.7
Orientation of Insertable Components	DEC STD 030	rule 6000
Orthographic Drawings, Multiview	ANSI Y14.3 - 1975	s 3-1
Outer Layers		
Conductors	DEC STD 030	rule 5240
Pads	DEC STD 030	rule 5260
Output, Standard Date Format	DEC STD 112	
Oven Module Baking		
Small	ELMF308-03	s 2.1
Walk in	ELMF308-03	s 2.2
Overlap, Wirewrap - Workmanship Criteria	DEC STD 116-6	s 5.0

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Subject	Reference	Subhead or other (as indicated)
Package Content requirements,		
Prototype Release	DEC STD 142-1	
Packaged Systems,		
Documentation	DEC STD 126	
Part Numbering	DEC STD 012-3	
Packaging Configuration, Gate		
Array Design	ELMP400-UG	s 7.1
Pads,		
Clearances	DEC STD 030	rule 5200
Clinched Leads	DEC STD 012-1	s 37.0
Heat Relief	DEC STD 030	table 14, rule 5280
Inner Layer Clearance	DEC STD 030	rule 5270
Lifted	DEC STD 116-1	s 10
Outer Layers	DEC STD 030	rule 5260
Spacing To Finger	DEC STD 030	rule 5050
Table of Sizes	DEC STD 030	table 14
Pad/Line Detail Specifications	DEC STD 030	table 14
Pad Size,		
Backplanes Wave-Soldered	DEC STD 030	rule 8410
Press-Pin Backplanes	DEC STD 030	rule 8530
Panel		
Inspection Procedure, Plated Thru Holes	7665009-00	
Overview	DEC STD 030	figure 8
Pantograph		
Handle	ELMF308-01	s 3.7.3
Insertion Machine	ELMF308-01	s 3.7.3
Safety Handle	ELMF308-01	s 3.7.3
Paper Tape Registration Test,		
Optical Comparator	7665090-00	
Parallel Bar Calibration Procedure	7665046-00 (obsolete)	
Part		
And Document Naming Conventions	DEC STD 006	
Data Entry Fields, Automated PL	DEC STD 025-2	s 2.3
Data Fields, Parts Lists	DEC STD 025-1	s 2.2
Identifier, Metal Fabrication Parts	DEC STD 012-7	s 2.1
Non-Metal Fabricated Parts	DEC STD 012-7	s 2.1
74-Class	DEC STD 012-7	s 2.1
Parts List,		
Automated	DEC STD 025-0	s 2.3
	DEC STD 025-2	

Subject	Reference	Subhead or other (as indicated)
Parts List, (cont'd)		
Automated Preparation	ELENKPL-UG	
Extended Matrix Format	DEC STD 025-0	s 2.3.2
	DEC STD 025-2	s 2.0
General Requirements	DEC STD 025-0	
Manual	DEC STD 025-0	s 2.2
	DEC STD 025-1	
Manual or Automatic Format Selection	DEC STD 025-0	s 2.1
Module Format	DEC STD 025-0	s 2.3.1
	DEC STD 025-2	s 2.0
Part Number,		
Cable and Harness Identification	DEC STD 021-0	
Field Service Assignment Convention	DEC STD 012-8	
Naming Conventions	DEC STD 006	
Purchase Specification	DEC STD 055	s 1.3.1
74-Class	DEC STD 012-7	s 3.1.1
Part Number Request Form (PNRF),		
Approval	DEC STD 055	s 1.3.1.2
Filling Out	DEC STD 055	s 1.3.1.1
Part Type, Master Part File Field	DEC STD 137	table 1
Partitioning, Gate Array Design	ELMP400-UG	Appendix b.2.1
Pattern, Standard Grid Layout	DEC STD 030	rule 5070
PAVES	DEC STD 059-1	
PC Process, Prototype - Overview	DEC STD 142-1	s 2
PDP-8, Omnibus Interface	DEC STD 157	
PDP-11		
Extended Instructions	DEC STD 168	
Unibus Interface	DEC STD 158	
PDP 11/45 MODULE,E XOR TEXT	7665089-00	
PDP-14, Inspection Procedure	7665092-00	
PDQ Code Development	DEC STD 030	figure 6
PDQ Form, Backplane	DEC STD 030	figure 14
PDQ Form, Module	DEC STD 030	figure 3
Phantom Drawing, Pictorial Drawings	ASA Y14.4 - 1957	s 4-14
Phase		
Review Process, Requirements	DEC STD 028	
Transition, Phase Review Process	DEC STD 028	
Physical Tests, Paints and Finishes	DEC STD 092	s 6.0
Photo Plotted Artwork	DEC STD 030	rule 5300
Pictorial Drawing,		
Documentation Practice	ASA Y14.4 - 1957	
Kinds	ASA Y14.4 - 1957	s 4-3
Uses	ASA Y14.4 - 1957	s 4-2
Pin		
Access, Test-Backplanes	DEC STD 030	rule 8600

Subject	Reference	Subhead or other (as indicated)
Pin (cont'd)		
Designation	DEC STD 030	rule 6060
Inserter -- Berg	ELMF308-01	s 3.10
Length, Backplanes	DEC STD 030	rule 8330
Spacing, Backplanes	DEC STD 030	rule 9320
Staked, Backplane	DEC STD 030	rule 8130
Pin 1 Determination	DEC STD 030	rule 6060
Place of Manufacture, Serial Number	DEC STD 031-2 7665070-00 (obsolete)	
Placement, Wire and Cable	DEC STD 116-4	s 10.0
Plain Plug Gauge, Calibration	7665040-00 (obsolete)	
Plant Capacity Model	ELMF308-00	s 4
Plant Code Identifiers, Serial Numbers	DEC STD 031-2	
Plant Start Up Check List	ELMF308-00	s 3, table 1
Plastic		
Handles, Routing Under	DEC STD 030	rule 6070
IC Packages, Auto insertion	DEC STD 030	rule 4140, 4150
Module Trays	ELMF308-01	s 3.1.7
Plated Thru Holes, Panel Inspection	7665009-00	
Backplanes	DEC STD 030	rule 8240
Plating, Gold Plate Process for Contacts	7665006-00	s 3.0
Plating, tin, thickness	DEC STD 030	rule 4060
Plotted artwork, positive	DEC STD 030	rule 5320
Pluggable Modules, Customer Return Inspection Criteria	DEC STD 264	s 4.6
Policy, Incoming Inspection	DEC STD 059-0	
Porosity, Gold Plating Process Test	7665005-00	s 4.4
Portable IC Stick Bin Unit Assembly	ELMF308-01	s 3.4.2
Positional Tolerancing, Advantages	ANSI Y14.5 - 1973	Appendix B
Formulas	ANSI Y14.5 - 1973	Appendix C
Positioning Components	DEC STD 030	s 6, rule 6000
Positive		
Plotted Artwork	DEC STD 030	rule 5320
And Negative plots, on same artwork	DEC STD 030	rule 5320
Potentiometers, Workmanship Criteria	DEC STD 116-5	s 8.0
Powder Metal,		
Bearings and Bushings	DEC STD 179-1	
Design Information	DEC STD 179-1	Appendix A
Designation on Drawings	DEC STD 179-1	s 2.0
Identification of Parts	DEC STD 179-1	s 6.0
Guidelines for Parts Design	DEC STD 179-2	Appendix
Structural Parts	DEC STD 179-2	

Subject	Reference	Subhead or other (as indicated)
Power		
Acceptance Stamps	7665096-00	
And Ground Connectors	DEC STD 030	figure 19, rule 5020
And Ground Finger Assignments	DEC STD 030	rule 5020,5030,5040
Bus, Splicing	7665098-00	
Control Model Acceptance	7665031-00	
Cord	7665297-00	
Customer Return Inspection Criteria	DEC STD 264	s 4.2
Delay Timer	7665030-00	
Design Guide	7665095-00	
General Design Guide	7665095-00	
Minimum Requirements	7665038-00	
Model Acceptance	7665031-00	
Shear - Hydraulic	ELMF308-04	s 2.6
Supply	7665030-00	
Test Procedure Format	7665024-00	
Workmanship Standards	7665038-00	
Pre-Baking Oven-Small	ELMF308-03	s 2.1
Pre-Baking Oven-Walk in	ELMF308-03	s 2.2
Pre-Design Producibility Responsibility	DEC STD 030	s 5.2.1, rule 2000
Predictions, Reliability	DEC STD 139	
Preferred IC Stick	ELMF308-01	s 3.4.2
Preforming Area	ELMF308-01	s 2.1
Pre-Release, Prototype PC	DEC STD 142-1	s 2.3
Press Pin Backplanes, Wirewrap Rules	DEC STD 030	s 8.2
Press Eyeletting - Airmite	ELMF308-04	s 4.2
Primary, AC Power	DEC STD 122	
Printed Circuit Board,		
Board Thickness	7665008-00	
Burnt	DEC STD 116-1	s 2.0
Cleaning	7665266-00 7665299-00	
Design Rules	DEC STD 030	s 5.2
Drilled Hole Size	7665007-00	
Final Model	7665039-00	
Inspection Alignment of Gold Contacts	7665002-00	
Layout, Backpanels	7665028-00	
Plated Thru Hole Panels	7665009-00	
Release Flow	DEC STD 142	
Scorched	DEC STD 116-1	s 2.0
Thickness-Inspection	7665008-00	
Tooling	7665194-00	
Use of Gauges	7665042-00	
Without Handles	7665029-00	
Printed Wiring		
Board, Acceptance Criteria	DEC STD 176	

Subject	Reference	Subhead or other (as indicated)
Printed Wiring (cont'd)		
Terminology	DEC STD 016	
Printsets, Field Maintenance	DEC STD 117	
Process,		
Compatibile Components	7665228-00	s 2.2
Controls, Gold Plate process	7665005-00	s 4.0
Documentation	ELMF308-00	s 1.4
	DEC STD 115	
Drilled Hole size vs Component Type	7665007-00	
Flow Diagram	ELMF308-00	figure 1
Gate Array Design	ELMP400-UG	Appendix B
Gold Plating Contacts	7665005-00	
Maturity Test	7665268-00	
Microfilm Creation and Distribution	DEC STD 033	
Overview, Fingerless Circuit Standards	DEC STD 030	figure 8
Resistance Soldering	7665012-00	
ROM/PROM Documentation	DEC STD 184	
Soldermask	7665004-00	
Standard Module Assembly Process	DEC STD 030	figure 7
Wirewrap Process	7665013-00	
Producibility		
Approval Process	DEC STD 030	s 2.1, rule 2000
Prototype Checking	DEC STD 142	s 3.3
	DEC STD 142-1	s 3.3
Requirements, General	DEC STD 030	s 2.1, rule 2000
Product		
Acoustic Noise, Acceptability	DEC STD 104	
Business Plans	DEC STD 130	
Designing to Eliminate Stock	7665120-00 (obsolete)	
Electrical Test Procedure	7665277-00	
Flame Testing Non-Metallic Part	7665288-00 (obsolete)	
Flammable Parts Test	7665257-00 (obsolete)	
Hold Procedure, Operational Alert	DEC STD 005-5	
	7665298-00	
Identification	DEC STD 031-0	
Line I.D. Label/Number Sticker	7665250-00	
Plastic Flammability Guide	7665264-00 (obsolete)	
Power Cord Caution Label	7665297-00 (obsolete)	
Quality Assurance Operation Alert	DEC STD 005-5	
Repetitive Informational and other	DEC STD 005-3	
Reporting Non Compliant Products	DEC STD 005-4	
Requirements	DEC STD 030	s 3
Safety	DEC STD 119	
Safety, In-plant Hold Procedure	DEC STD 005-6	
Serialization	DEC STD 031-0	
Standard UL Investigation Procedure	7665086-00 (obsolete)	
Technical	DEC STD 005-1	

Subject	Reference	Subhead or other (as indicated)
Product (cont'd)		
Types and Conditions	DEC STD 005-0	
Variation Changes, Serial Number	DEC STD 031-1	
Waivers, Product Line	DEC STD 005-2	
Program Management Standards,		
Design Review Process	DEC STD 007	
Phase Review Process	DEC STD 028	
Product Business Plans	DEC STD 130	
Project Scheduling	DEC STD 008	
Project Specification	DEC STD 009	
Programmable Devices, Documentation	DEC STD 184	
Project,		
Scheduling	DEC STD 008	
Specification	DEC STD 009	
Project Management,		
Business Plans	DEC STD 130	
Design Review	DEC STD 007	
Project Scheduling	DEC STD 008	
Project Specifications	DEC STD 009	
PROM, Programming Data I/O	7665274-00	
Proprietary Information, Publications	DEC STD 197	
Protocol,		
Data Access	DEC STD 189	
DDCMP	DEC STD 121	
Maintenance Operation	DEC STD 191	
Network Services	DEC STD 190	
Prototype, Etch Board and Module Release	DEC STD 142-1	
PRTINQ Program	ELENKPL-UG	s 14.0
PRTLST,		
Functions	ELENKPL-UG	s 1.5
Program	ELENKPL-UG	
Publications, Legal Guidelines	DEC STD 197	
Pulse Transformer	7665198-00 (obsolete)	
Punched Card Format	DEC STD 151	
Purchase Specifications,		
Definitions	DEC STD 055	s 2.1
Format	DEC STD 055	s 2.2
General Requirements	DEC STD 055	s 2.0
Preparation and Control	DEC STD 055	s 1.0
Responsibilities and Control	DEC STD 055	s 1.3
Writing Conventions	DEC STD 055	s 2.3

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Subject	Reference	Subhead or other (as indicated)
Quad	DEC STD 030	figure 12
Quality Assurance,		
Operational Alert (OPAL)	DEC STD 005-5	
Plotted Master Artwork	DEC STD 034	
Quality		
Assurance Procedures, Incoming Inspection	DEC STD 059	
Control Measurement System	7665142-00	
Finish and Color	DEC STD 092-0	
Of Appearance, Paints and Finishes	DEC STD 092	s 2.0
Requirements, Microforms	DEC STD 162	
QC Form 1011, Procedure for Handling, Storing and Packaging Chromicoated Parts and Assemblies	7665003-00	s 2.0
QC Form 1032, Wirewrap Inspection Report	7665001-00	s 2.0
QC Procedure,		
Acceptance	7665031-00	
Angle Iron and Plate Calibration	7665059-00 (obsolete)	
OPCOA Automatic LED Tester	7665074-00	
Control of Fixtures Used in Core Memory Stack Inspection	7665085-00	
Depth Micrometer Calibration	7665055-00 (obsolete)	
Dial and Test Indicator Calibration	7665058-00 (obsolete)	
Dial Push/Pull Gauge Calibration	7665048-00 (obsolete)	
Dial Vernier Calibration	7665053-00 (obsolete)	
Fabrication Shops	7665060-00	
Finish Specification Sheet metal Aluminum with Chromicoat Finish	7665019-00	
OPCOA Automatic LED Tester		
PDP-14 Inspection	7665092-00	
Power Supply-Control Model Tektronix 453 O'scope Calibration	7665094-00 (obsolete)	
Vernier Caliper Calibration	7665054-00 (obsolete)	
Wire Insulation Pull Test	7665047-00	
Wirewrap Tooling Calibration	7665027-00	
QT Release Process	DEC STD 142-1	

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Subject	Reference	Subhead or other (as indicated)
Rack Format, Gear Drawing	ANSI Y14.7.1 - 1971	s 7-5
Reel		
Holding Shelving	ELMF308-01	s 3.5.2
Identification Label - Sequencer	ELMF308-01	s 3.5.3
Reference Designations,		
Standard	DEC STD 030	rule 6150
Test Hole	DEC STD 030	rule 6160
Reference Specifications and Drawings		
Module Manufacturing	DEC STD 030	table 2
Release Procedure, 74 Class Part Number Documentation	DEC STD 012-7	s 3.1.6
Reject Codes, Plated Thru Hole Panel Inspection	7665009-00	
Release,		
Low Volume PC Board Process	DEC STD 142-2	
LSI/VLSI Documentation	DEC STD 027	
Module	DEC STD 142	
Printed Circuit	DEC STD 142	
Programmable Devices	DEC STD 184	
Prototype Process	DEC STD 142-1	
Reliability MTBF	7665180-00 (obsolete)	
Process Maturity Test	7665268-00	
Design Maturity Test	7665268-01	
Operational Alert/Product Hold Procedure	7665298-00	
Predictions	DEC STD 139	
Relieving Large Copper Planes	DEC STD 030 figure 30,	rule 5290
Reject Board Sticker	ELMF308-01	s 3.4.3, 3.6.3
Removable Diskpack, Disk Systems, Volume Identification	DEC STD 167	
Repair,		
Backplane Assemblies	7665034-00	
Connector Blocks	7665034-00	
Modules	7665197-00 (obsolete) DEC STD 265	
Replacement Charts, Diode and Transistor DIPS	7665035-00 (obsolete)	
Restricted Fingers	DEC STD 030	rule 5030
Restrictions, Gate Array Design Loading	ELMP400-UG	s 3.6

Subject	Reference	Subhead or other (as indicated)
Requirements, Software Manuals		
Describing Licensed Software	DEC STD 172	s 2.1
Resistance Soldering, Process Specification	7665012-00	
Resistors - Identification	DEC STD 116-8	s 2.6
Responsibilities,		
Legal Notices	DEC STD 172	s1.3.2-4
Purchase Specifications	DEC STD 055	
Restricted Distribution, Labelling	DEC STD 128	
Retaining Hardware and Mechanical Fastener's	DEC STD 116-5	
Revision,		
Drawings	DEC STD 014	
Magnetic Media Control	DEC STD 185	
Revision History, Automated Parts List	DEC STD 025-2	s 2.5
Revision Matrix, DD	DEC STD 024-1	s 3.1
Rework and Repair Area	ELMF308-04	s 2.7
Rework, Wirewrap		
ECO	7665013-00	
Module	DEC STD 265	
Re-zero hole, Fingerless Circuits	DEC STD 030 figure 13, rule 2021	
Re-zero Option	ELMF308-01	s 3.4.2, 3.6.4
RK06, Bad Sector Detection	DEC STD 144	
RK07, Bad Sector Detection	DEC STD 144	
Rosin Bonds	DEC STD 116-1	s 38.0
Rotary Board Slitter	ELMF308-04	s 2.2
Routing Under Plastic Handles	DEC STD 030	rule 6070
Routing, Wire and Cable	DEC STD 116-4	s 10.0
Rubber Matting In Wave Solder Area	ELMF308-00	table 19
Rules Summary, General Module Design and Manufacturing Rules	DEC STD 030	s 2.3
RX01 Floppy Disk, Volume Identification	DEC STD 154 (obsolete)	

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Subject	Reference	Subhead or other (as indicated)
Safety		
Grounding, AC Power Wiring	DEC STD 002	
Rules, Product Safety Compliance	DEC STD 030	rule 3000
5 Gal. Cans	ELMF308-03	s 2.3.3
Workmanship Criteria	DEC STD 116-7	s 1.0
SAGE2, Gate Array Design	ELMP400-UG	s 1.3.1.2
Sample Size, Module Inspection	7665039-00	
Sampling Plans	MIL-STD-105 7665079-00 (obsolete)	
AC Parametric Testing SSI/MSI Devices	7665357-00	
Screw,		
Adjusting - Workmanship Criteria	DEC STD 116-5	s 7.0
Flat head - Workmanship Criteria	DEC STD 116-5	s 5.0
Protrusion - Workmanship Criteria	DEC STD 116-5	s 2.0
Thread Representation	ANSI Y14.6 - 1978	
SDC, Software Boxes	DEC STD 129	
Second Choice "L" Code Machine Part	DEC STD 030	table 9, rule 4031
Section Numbering, Software Manuals	DEC STD 117	
Sections,		
Extended Matrix Parts List	DEC STD 025-2	s 2.4.2
Manual Parts Lists	DEC STD 025-1	s 2.4
Module Parts List	DEC STD 025-2	s 2.4.1
Sectional Views,		
Documentation Practice	ANSI Y14.3 - 1975	s 3-3
Pictorial Drawings	ASA Y14.4 - 1957	s 4-6
Selection		
Guide, Standard Circuit Technology	DEC STD 030	table 3
Review, and approval process flow chart	DEC STD 030	figure 2
Sequence,		
Escape Standard	DEC STD 110	
Reel Identification Label	ELMF308-01	s 3.5.3
C/C Axial Component	ELMF308-01	s 3.5
Centering Alignment Fixture	ELMF308-01	s 3.5.2
Serial Numbering, Product	DEC STD 031-0	
Shading, Pictorial Drawings	ASA Y14.4 - 1957	s 4-12
Shear line visual-Fingerless Circuits	DEC STD 030	figure 13, rule 2021
Shearing Requirements	DEC STD 030	rule 5230
Shelving - Reel Holding	ELMF308-01	s 3.5.2, 3.6.2

Subject	Reference	Subhead or other (as indicated)
Shorts, Solder	DEC STD 116-1	s 29.0
Shortship, Software Box	DEC STD 129	s 6.0
Side Identification	DEC STD 030	rule 5014
Signal Integrity, Design Considerations	DEC STD 186	
Signatures,		
Automated Parts Lists	DEC STD 025-2	s 2.2
Parts Lists	DEC STD 025-1	s 2.3
Silk Screen		
Artwork Process	7665233-00	
8/I Back Panel Identification	7665014-00	
Soldermask Process	7665004-00	s 3.2
Single	DEC STD 030	figure 12
Sided panel, Inspection Criteria	7665026-00	
Sided PC Board, Backpanel	DEC STD 030	s 8
Sizes,		
Drawing	DEC STD 013	
Standard 0.125 inch finger circuits	DEC STD 030	figure 12
Standard fingerless circuits	DEC STD 030	figure 11
Sleeving, Harnesses	DEC STD 116-4	s 8.0
Slide-a-long Assembly	ELMF308-02	s 2.3.3
Slitter - Automatic Positioning Table	ELMF308-04	s 2.2
Slitter- 36 Inch Rotary	7665263-00	
Smog Hog Filtration Unit	ELMF308-03	s 2.4
Software,		
Wirewrap	DEC STD 181	
Software And Architecture Standards,		
BASIC	DEC STD 150	
Cassette Format Standard for Labelled and Unlabelled Files	DEC STD 125	
COBOL	DEC STD 152	
Data Access Protocol	DEC STD 189	
DDCMP	DEC STD 121	
DECtape II Interchange Volume Format	DEC STD 196	
Disk Standard for Recording and Handling Manufacturing Detected Bad Sectors	DEC STD 144	
Diskpack Systems	DEC STD 167	
Documenting System Messages	DEC STD 170	
Documentation symbology	DEC STD 165	
Error Logging	DEC STD 153	
Floppy Disk	DEC STD 154 (obsolete)	
LSI Bus	DEC STD 160	
Magnetic Tape Read/Write Errors	DEC STD 174	
Maintenance Operations Protocol	DEC STD 191	
Massbus	DEC STD 159	
Naming System Software Products and Release	DEC STD 173	

Subject	Reference	Subhead or other (as indicated)
Software and Architecture Standards (Cont'd)		
Omnibus	DEC STD 157	
PDP-11 Extended Instructions	DEC STD 168	
Punched Card Format	DEC STD 150	
Standard Coded Character Set	DEC STD 051	
Standard Date Format for Output	DEC STD 112	
Standard for Escape Sequence	DEC STD 110	
Standard for Indexes, Appendixes, Running Heads and Section Numbering for Software Documentation	DEC STD 118	
Standard for Registration of Control Characters, Escape, and Control Sequences	DEC STD 138	
Standard for Terminal Synchronization	DEC STD 111	
Standard for Updating Hardware/ Software Manuals	DEC STD 143	
Terminal Keyboards	DEC STD 107	
UNIBUS	DEC STD 158	
VAX Architecture	DEC STD 032	
VAX-11 Procedure Calling and Condition Handling Standard	DEC STD 011	
Software Box	DEC STD 129	
Software Distribution Center, Part Numbering	DEC STD 012-4	
Software Engineering,		
BASIC	DEC STD 150	
Cassette Format	DEC STD 125	
COBOL	DEC STD 152	
Digital Magnetic Labels	DEC STD 149	
Disk Standard for Detected Bad Sectors	DEC STD 144	
Documenting Systems Message	DEC STD 170	
Error Logging Standard	DEC STD 153	
Escape Sequences	DEC STD 110	
File Structure	DEC STD 149	
Floppy Disk Volume Identification and Data Interchange	DEC STD 154	(obsolete)
Hardware and Software Editing	DEC STD 147	
Magnetic Tape Error Recovery	DEC STD 174	
PDP11 Extended Instructions	DEC STD 168	
Punched Card Format	DEC STD 151	
Registration Control of Control Characters, Escape and Control Sequences	DEC STD 121	

Subject	Reference	Subhead or other (as indicated)
Software Engineering (cont'd)		
Removeable Diskpack Disk Systems Volume Identification	DEC STD 167	
Representation of Data Values in ASCII Character Strings	DEC STD 145 (obsolete)	
Standard Code Character Set	DEC STD 051	
Standard Date Format	DEC STD 112	
Terminal Keyboard	DEC STD 107	
Terminal Synchronization	DEC STD 111	
User Mode Diagnostics	DEC STD 148	
VAX Architecture	DEC STD 032	
Software Manuals, Legal Notices	DEC STD 172	
Software Module Within Source, Legal Notices	DEC STD 172	s 2.4.1
Software Publications		
Documenting Systems Messages	DEC STD 170	
Documentation Symbology	DEC STD 165	
Solder,		
Excessive	DEC STD 116-1	s 32.0
Gloves	ELMF308-03	s 2.3.3
Joint, Fractured	DEC STD 116-1	s 36.0
Mask Assembly	ELMF308-03	s 2.3.3
Projections	DEC STD 116-1	s 39.0
Requirements, Print and Etch Modules	DEC STD 116-1	s 35.0
Resist	7665189-00	
Splashes	DEC STD 116-1	s 38.0
Suckers (Anti-static)	ELMF308-02	s 2.5.3
Touch-Up Specifications	ELMF308-03	s 3
Touchup-Specification	7665010-00	
Wave	7665158-00	
Wave Conveyor Lift System	ELMF308-03	s 2.3.4
Wave Machine	ELMF308-03	s 2.3
Wave Process Specifications	ELMF308-03	s 2.3.5
Soldered Terminations, Workmanship	DEC STD 116-1	
Soldering,		
Backplane	7665236-00	
Resistance	7665012-00	
Soldermask,		
Backplanes	DEC STD 030	rule 8010
Epo-Tech Green	7665003-00	s 2.7
Inspection Procedure	7665006-00	
Process Specification	7665004-00	
Water Soluble	ELMF308-02	s 2.5
Water Soluble - Dispenser	ELMF308-02	s 2.5
Solvent - Cleaning	ELMF308-04	s 2.7
Space Analyses and Applications	ANSI Y14.3 - 1975	Appendix B
Space Geometry	ANSI Y14.3 - 1975	Appendix A

Subject	Reference	Subhead or other (as indicated)
Spacer, Radial Lead Components	DEC STD 116-1	s 23.0
Spacing,		
Pads to Board Edge	DEC STD 030	
Fingers To Pads	DEC STD 030	rule 5050, figure 19
Pads to Mounting Hardware	DEC STD 030	rule 6100
Spare Fingers	DEC STD 030	rule 5040
Special Features Library General Description	ELEN302-00	s 7.1
Specifications		
Approved DEC Finishes	DEC STD 092	
Finished Circuits	DEC STD 030	figure 25
Referenced Guide Module Mfg	DEC STD 030	table 2
Spiral Wraps	DEC STD 116-6	s 6.0
Splice clip	ELMF308-01	s 3.5.3, 3.6.3
Splicing, Power Bus	7665098-00	
Split Lug		
Eyelet Machine	ELMF308-01	s 3.3
Insertion	ELMF308-01	s 3.1.2
Spring Hooks For DIP Machine	ELMF308-01	s 3.4.3
Spring Socket Machine - AMP	ELMF308-01	s 3.9
Spur Format, Gear Drawing	ANSI Y14.7.1 - 1971	s 7-5
Stainless Steel Lab Cans	ELMF308-03	s 2.3.3
Staked Pins, Backplane	DEC STD 030	rule 8130
Stamping		
Machine - Metal Handle	ELMF308-04	s 3.2
Machine - Plastic Handle	ELMF308-04	s 3.1
Castings	DEC STD 030	rule 8100
Standard		
Cost, Master Part File Field Elements	DEC STD 137	table 1
Covers, IDEA	ELEN302-00	s 5.4
Density, Module Outlines and EIC	DEC STD 030	table 4
Density, Pad Sizes	DEC STD 030	table 14
Density, Unity Cost	DEC STD 030	table 5
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Drilled Hole Sizes, PCB's	7665007-00	
Features, File Name Format	ELEN302-00	s 5.4.7
Features Library, General Description	ELEN302-00	s 7.1
Fingerless Module Sizes	DEC STD 030	figure 11
Grid, Component Mounting	DEC STD 030	s 5.3.1
Grid, Layout	DEC STD 030	figure 21, s 5.3
Grid, Rules	DEC STD 030	s 5.3, rule 5070
Labor Settings For Module Assembly and Test	ELMF308-00	s 1.4.5
Layer Technology Choices	DEC STD 030	figure 10
Module Assembly Process	DEC STD 030	figure 7

Subject	Reference	Subhead or other (as indicated)
Standard (cont'd)		
Module Assembly Process Flow Diagram	ELMF308-00	figure 1
Orientation, DIPS	DEC STD 030	figure 13
Stanford University Drawing System (SUDS), Computer Media Identification	DEC STD 194	
Stick Bin Assembly	ELMF308-01	s 3.4.2
Stick IC - Preferred	ELMF308-01	s 3.4.2
Stick key	ELMF308-01	s 3.4.2
Stick Plug Puller	ELMF308-01	s 3.4.2
Strain Relief, Wire and Cable	DEC STD 116-4	s 9.0
SUDS,		
Gate Array Design	ELMP400-UG	s 1.3.1.1
Library, File Name Format	ELEN302-00	s 4.7
Library, Gate Array Cell Configuration	ELMP400-UG	figure 2-4
Library, General Description	ELEN302-00	s 4.1
Switches - Workmanship Criteria	DEC STD 116-5	s 8.0
Symbology,		
Dimensioning and Tolerancing	ANSI Y14.5 - 1973	s 5-3
Schematic	DEC STD 056	
Software Documentation	DEC STD 165	
Symbols,		
Brazing	ANSI/AWS A2.4 - 1979	
Geometric Characteristics	ANSI Y14.5 - 1973	Appendix D
Nondestructive Testing	ANSI/AWS A2.4 - 1979	
Welding	ANSI/AWS A2.4 - 1979	

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Subject	Reference	Subhead or other (as indicated)
Table of Insertion Codes	7665228-00	s 3.2
Tantalum Capacitors, Avoiding Use	DEC STD 030	rule 4000
Tape		
Blue 0.25 inches x 180 yards	ELMF308-01	s 2.4.2
Blue 0.25 inches x 3,520 yards	ELMF308-01	s 3.5.3
Folders - Manila	ELMF308-01	s 3.4.2
White 0.25 inches x 180 yards	ELMF308-01	s 2.4.2
White 0.25 inches x 3,520 yard	ELMF308-01	s 3.5.3
Technical Documentation,		
Hardware Manuals	DEC STD 003	

Subject	Reference	Subhead or other (as indicated)
Technical Documentation, (cont'd)		
Typeset Media	DEC STD 124	
Technology		
Four Standard PCB Choices	DEC STD 030	figure 10
Standard Circuit	DEC STD 030	table 3
Tempil Sticks	ELMF308-03	s 2.3.3
Template, Insertion	DEC STD 030	rule 8580
Templates, Machine-Control	7665060-00	
Teradyne,		
Continuity Tester	ELMF308-05	s 2.3
J259/S2575 Test	7665164-00	
J384, Test	7665230-00	
L427 Continuity Tester	ELMF308-05	s 2.1.2
T317, Test	7665272-00	
Terminals,		
Bifurcated	DEC STD 116-2	s 7.0
Closed Barrel - Workmanship Criteria	DEC STD 116-3	s 4.0
Cup	DEC STD 116-2	s 8.0
Escape Sequence Standard	DEC STD 110	
Keyboard Synchronization	DEC STD 111	
Open Barrel - Workmanship	DEC STD 116-3	s 3.0
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Synchronization, Standard	DEC STD 111	
Termination,		
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Terminal Tab	DEC STD 116-2	s 9.0
Terminology, Printed Wiring	DEC STD 016	
Test		
And Repair Hand Soldering Recommendation	ELMF308-03	s 3.3
Capability Backpanel	DEC STD 030	rule 8200
Fixtures, press-pin backplane	DEC STD 030	rule 8620
Fixturing, BATS	DEC STD 030	rule 8620
Hole, Reference Designations	DEC STD 030	rule 6160
Method, Adhesion-Gold Plating	7665005-00	s 4.5
Method, Porosity-Gold Plating	7665005-00	s 4.4
Patterns, Gate Array	ELMP400-UG	s 6.3
Pattern Generator, Gate Array Design	ELMP400-UG	s 6.1
Procedure, 704 Power Supply	7665041-00	
Program Generation Tools, Gate Array Design	ELMP400-UG	s 6.2
Systems, press-pin backplane	DEC STD 030	rule 8610
Testability Guidelines, Gate Array Design	ELMP400-UG	Appendix A-2
Testing, Manufacturing Operations Plan	DEC STD 101	

Subject	Reference	Subhead or other (as indicated)
TH center, requirements, Fingerless Circuits	DEC STD 030 figure 13	rule 2021
Thermal		
Calculations,	DEC STD 120	
Compound	DEC STD 116-5	s 4.0
Shock		
Water Bath and Drying Oven	7665066-00	
Liquid Medium	7665182-00	
Thermometer - Solder Wave	ELMF308-03	s 2.3.3
Thickness,		
Contact Area-Inspection	7665009-00	
Gold Plating-Inspection	7665009-00	
Gold Plating Process	7665005-00	s 4.3
PCB-Inspection Procedure	7665008-00	
Press-pin backplanes	DEC STD 030	rule 8510
Thinner,		
Chemical Safety Data	ELMF308-03	s 2.3.8.1
Flux	ELMF308-03	s 2.3.3
Thread Representation, Pictorial Drawings	ASA Y14.4 - 1975	s 4-9
Tie Wraps,		
Connectors	DEC STD 116-4	s 7.0
Harness Bundling	DEC STD 116-4	s 6.0
Spacing	DEC STD 116-4	s 6.3
Tin Plating	DEC STD 030	rule 4060
Tinning, Wire	DEC STD 116-2	s 3.0
Titanium Finger Clips	ELMF308-03	s 2.3.3
Title Block,		
Automated Parts List	DEC STD 025-2	s 2.1
Manual Parts Lists	DEC STD 025-1	s 2.1
Tolerances,		
Form and Runout	ANSI Y14.5 - 1973	s 5-6
Location	ANSI Y14.5 - 1973	s 5-5
Iron Castings	DEC STD 020	
Powder Metal Dimensional	DEC STD 179-1	Appendix A.2
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Tooling		
Feature	DEC STD 030	table 13
Holes, Backplanes	DEC STD 030	rule 8550
Tooling Plates	ELMF308-01	s 3.4.2, 3.6.2
Tools		
ECO and Retrofit	ELMF308-02	s 3.2
Hand Assembly	ELMF308-02	s 2.2
Maintenance	ELMF308-02	s 2.2.1
Top Document, DD	DEC STD 024-1	s 2.2.2
Touch-up,		
Area Floor Layout	ELMF308-03	s 2.7.2